



Ultimate Low-Light Level Sensor Development

SiPM mini-school  
Ringberg, Tegernsee

# SiPM State-of-the-art

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Moscow Engineering and Physics Institute

19-21 June 2019



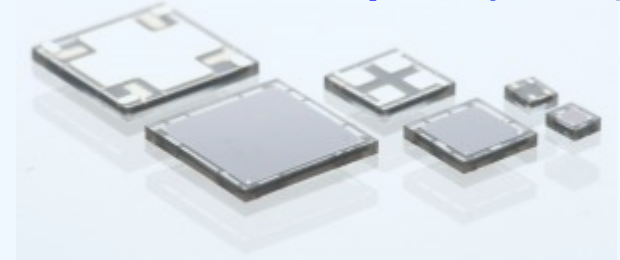
# Content

- What is a SiPM?
- Main SiPM parameters
- SiPM Zoo at the time being
- Trends for further SiPM development



**Vacuum photomultiplier (PMT)**

### Silicon Photomultiplier (SiPM)



- Compactness
- Low weight
- Low power consumption ( $\sim 50 \mu\text{W}$ )
- Low voltage supply (20-100V)
- Fast signal ( $\sim 1 \text{ ns}$  front)
- Simple FE electronics
- Room temperature operation
  - Sensitivity to single photons
  - Possibility to measure light intensity
  - Excellent amplitude resolution
  - Negligible nuclear counting effect
  - Immunity to magnetic fields up to 7 T

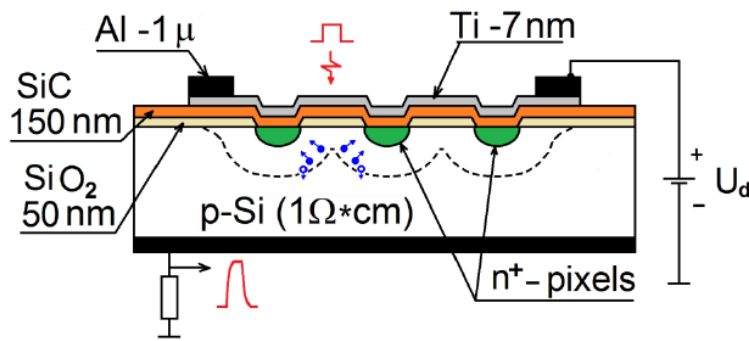
***SiPM is a novel type of photon number resolving limited Geiger-mode solid state photodetector***

# Silicon Photomultiplier (SiPM)

Around 1990 the initial prototypes of SiPM (**MRS** Metal- Resistor Semiconductor APD's) were invented in Russia (V.Golovin,Z.Sadygov,N.Yusipov (Russian patent#1702831, from 10/11/1989)

This invention was preceded by basic studies of Avalanche with Negative Feedback (ANF) at Lebedev Physical Institute in Moscow ) leaded by Dr. V.Shubin concerned to (1970s-1990s)

Avalanche Photodetectors. Vitaly E. Shubin, Dmitry A. Shushakov Encyclopedia of Optical Engineering  
DOI: 10.1081/E-EOE 120009727



The first MRS samples had :

- Too difficult and unreproducible technology
- Too low light detection efficiency (of about 1%)
- Unclear operational principle

A.V. Akindinov et al, NIM A 387 (1997) 231

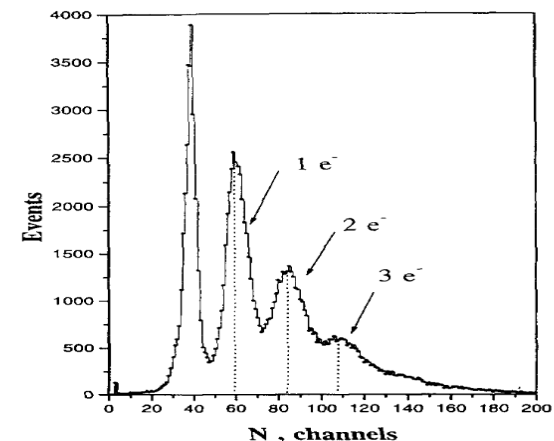


Fig. 3. Pulseheight spectrum from LED at 0°C (epitaxial sample).

But nevertheless they looked very promising detectors for Experimental Physics due to their ability to detect single photons and moreover to resolve number of photons!



# Homage of Boris Dolgoshein (1930-2010)



**Professor MEPHI**

**Head of the particle-physics  
department of MEPHI**

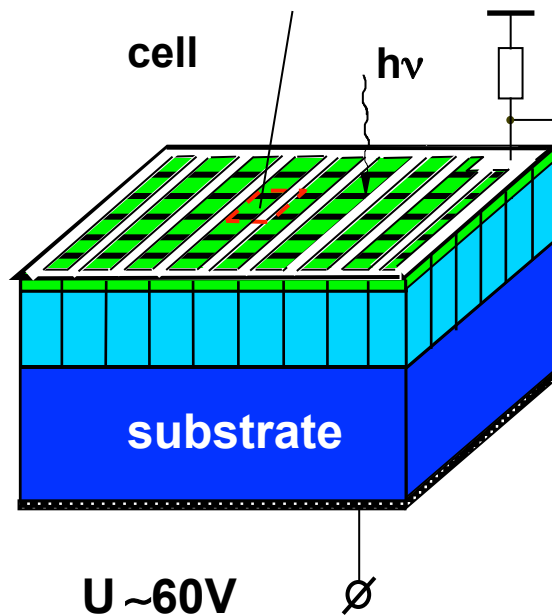
**Inventor of streamer chamber (1962)**

**Developer and pioneer of Transition  
Radiation Detector (TRD)**

prof. Dolgoshein started to develop a novel photodetector which he called  
Silicon Photomultipliers (SiPM) since 1993

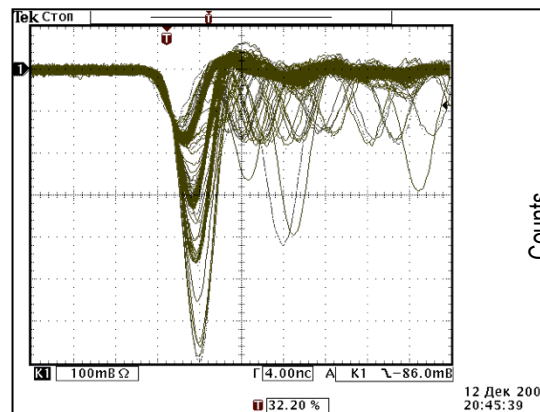
*Now we have at MEPHI the well equipped the Silicon Photomultipliers  
laboratory with ~ 30 employees*

# Silicon Photomultiplier

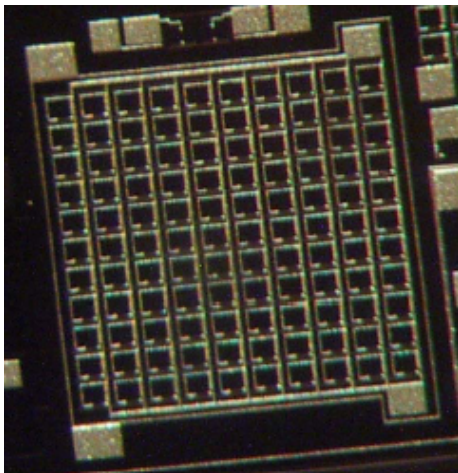
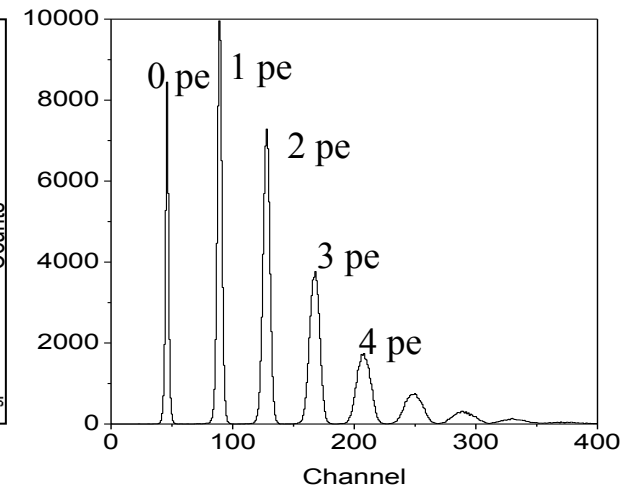


Multicell device with common readout

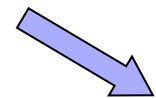
Scope signal



Amplitude spectrum



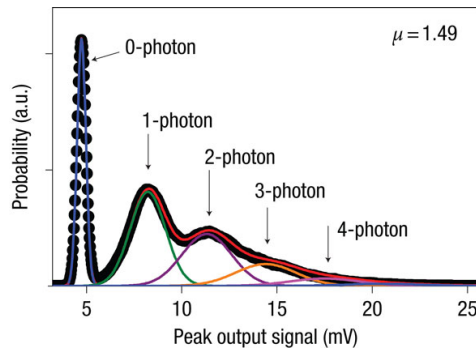
- Each cell – p-n-junction in selfquenching Geiger mode
- cell numbers:  $\sim 100 \div 10000/\text{mm}^2$
- All cells are equal
- Cells are independent from each other
- Signal – is a sum of all fired cells



Cell signal - 0 or 1  
But SiPM is analogue device

# SiPM: photon number resolution

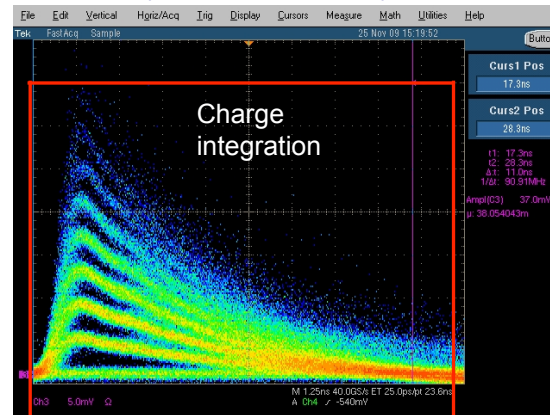
APD (self-differencing mode)



B. Cardinal et al., Nat. Photonics, 2008

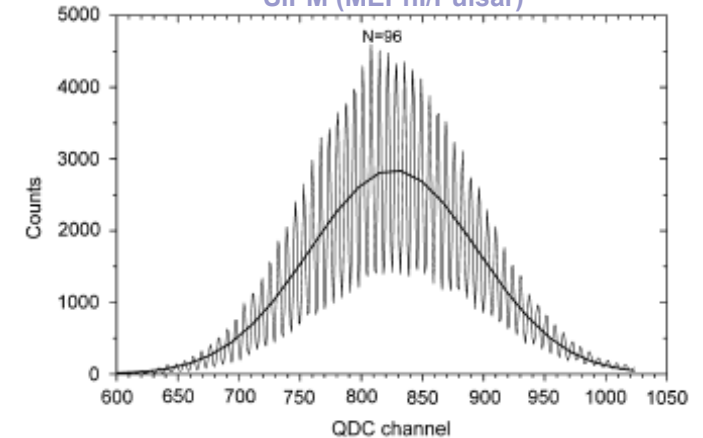
APD QE ~ 80%

SiPM (Hamamatsu MPPC)



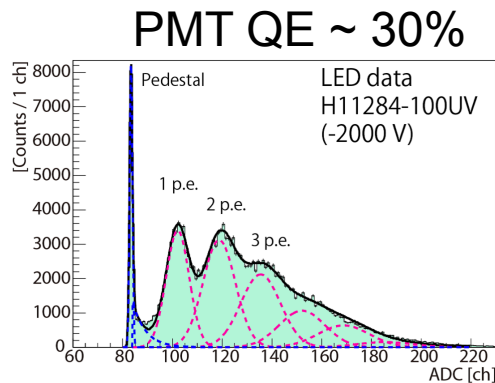
SiPM PDE ~ 30%

SiPM (MEPhI/Pulsar)



R. Mirzoyan et al., NDIP, 2008

PMT (Hamamatsu H11284-100UV)



PMT QE ~ 30%

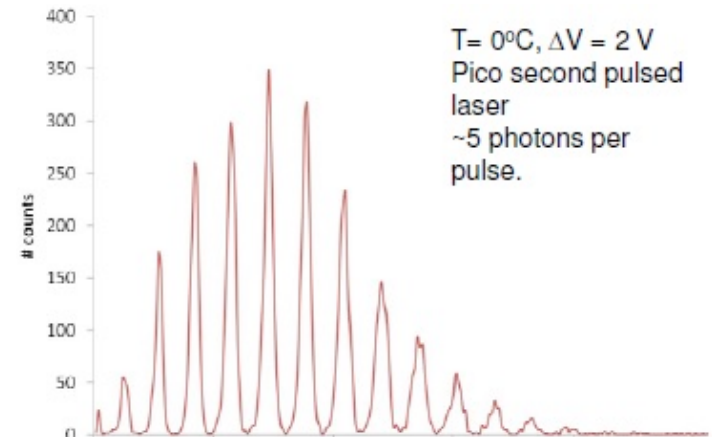
T. Cogami et al, Water Cherenkov detector,  
NIMA 2016

SiPM (Hamamatsu MPPC)



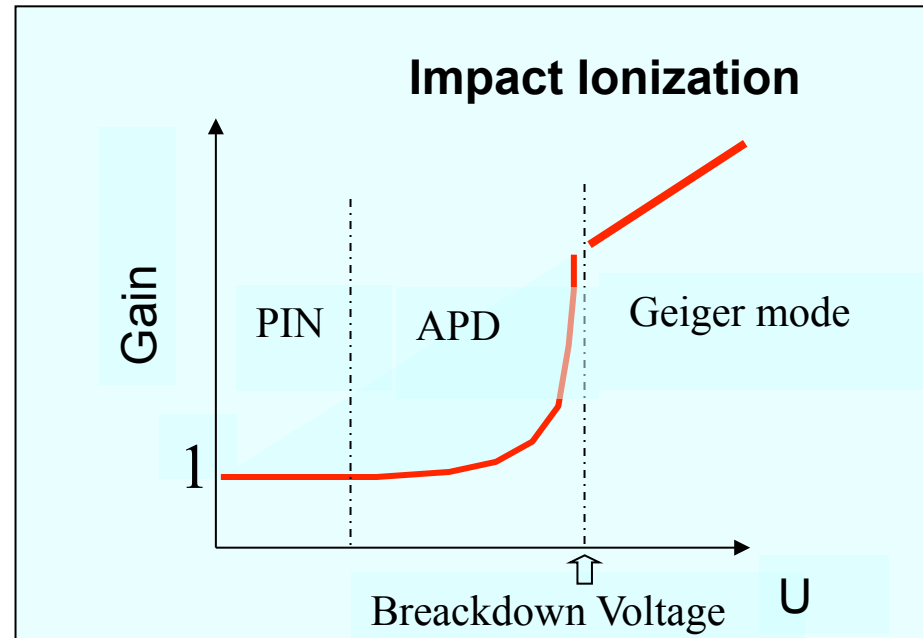
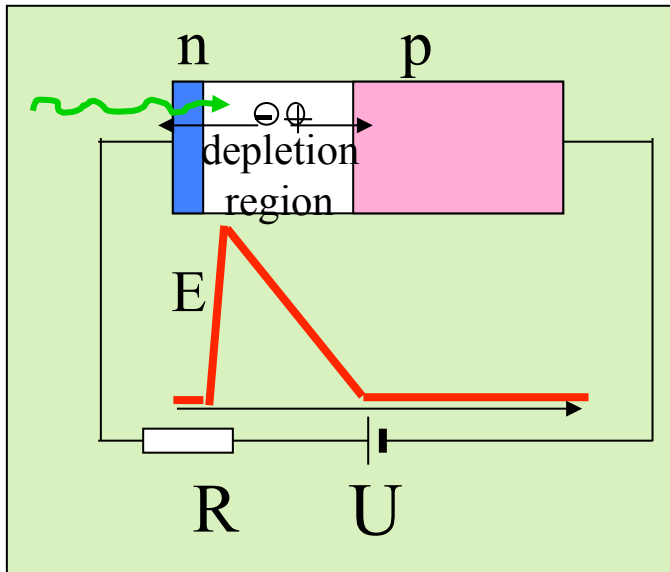
S. Vinogradov, SPIE 2017

SiPM (Excelitas by MPI/MEPhI license)



A. Barlow and J. Schilz, SiPM matching event,  
CERN, 2011

# p-n-junction based detectors



## Geiger discharge

- Output signal doesn't depend from input signal
- Output signal value  $Q$  is determined by charge accumulated on a pixel capacitance
- Discharge duration  $< 1$  ns
- self-quenching due to the quenching resistor

$$Q = C_{\text{cell}} \cdot (V - V_{\text{breakdown}})$$

$$\Delta V = (V - V_{\text{breakdown}}) - \text{overvoltage}$$

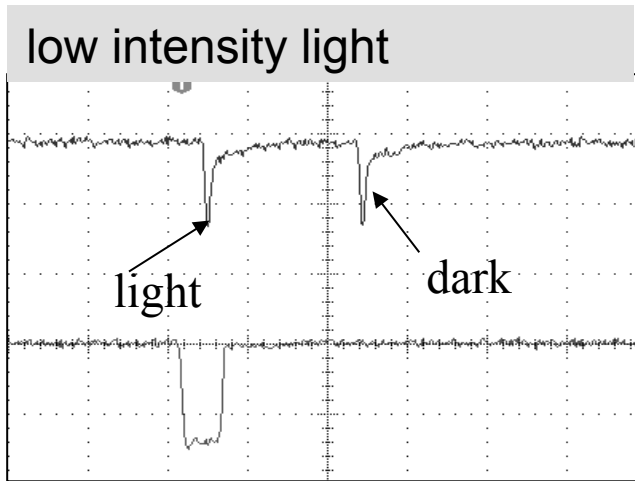
$$M = Q/e - \text{microcell gain}$$

$$M = 10^5 - 10^6$$

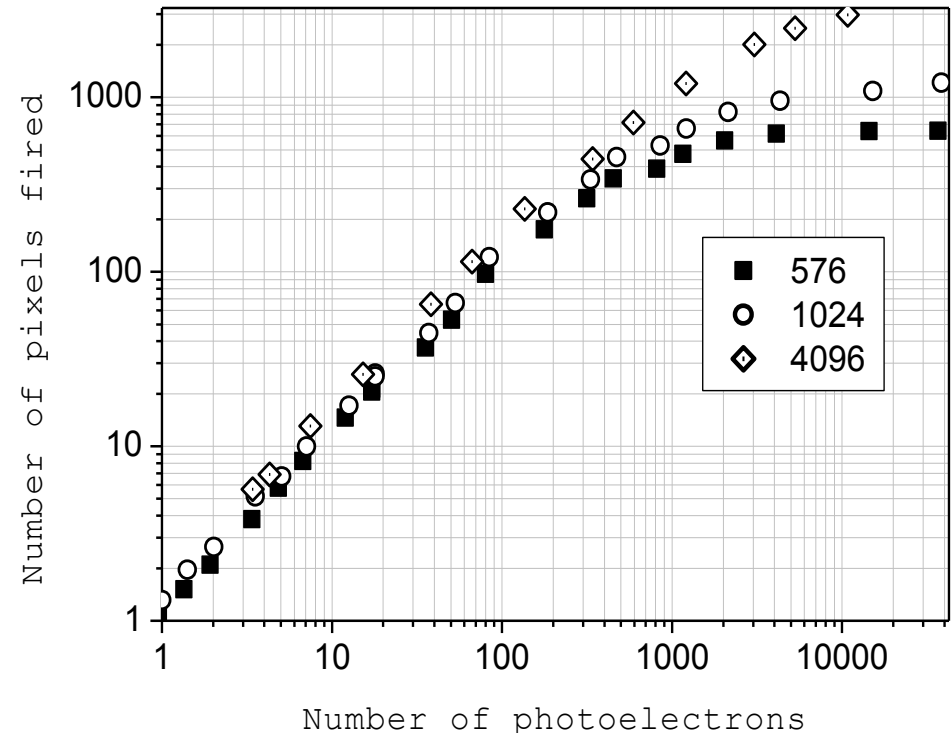
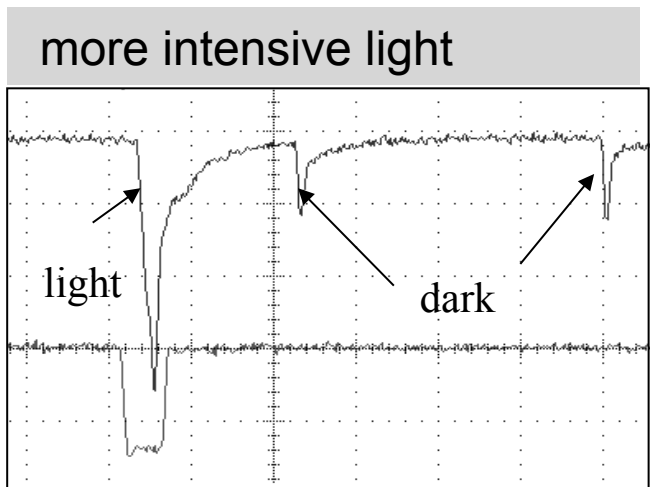
# Silicon Photomultiplier (SiPM)

## Response function for SiPMs with different microcells numbers

V. Andreev et al. / NIM A 540 (2005) 368–380



“light” and “dark” signals are identical



$$N_{firedcells} = N_{total} \cdot \left[ 1 - e^{-\frac{N_{photon} \cdot PDE}{N_{total}}} \right]$$

- Response function depends on total number of microcells inside SiPM
- Saturation correction is possible

# Main SiPM's parameters

- Photon Detection Efficiency **PDE**  $\longrightarrow$  Primary events

$$PDE = \frac{\langle N_{\text{fired\_cell}} \rangle}{\langle N_{\text{photons}} \rangle} \quad P(n, \lambda) = \frac{\lambda^n e^{-\lambda}}{n!} \quad \langle N_{\text{cell}} \rangle = -\ln P(0, \langle N_{\text{cell}} \rangle) \quad \text{Important – no signal, no crosstalk!!!}$$

- Dark rate **f** =  $\langle n_{\text{dark}} \rangle / T$ ,  
where T – integration time

- Gain **G**

- Crosstalk **xt** (afterpulsing **ap**)

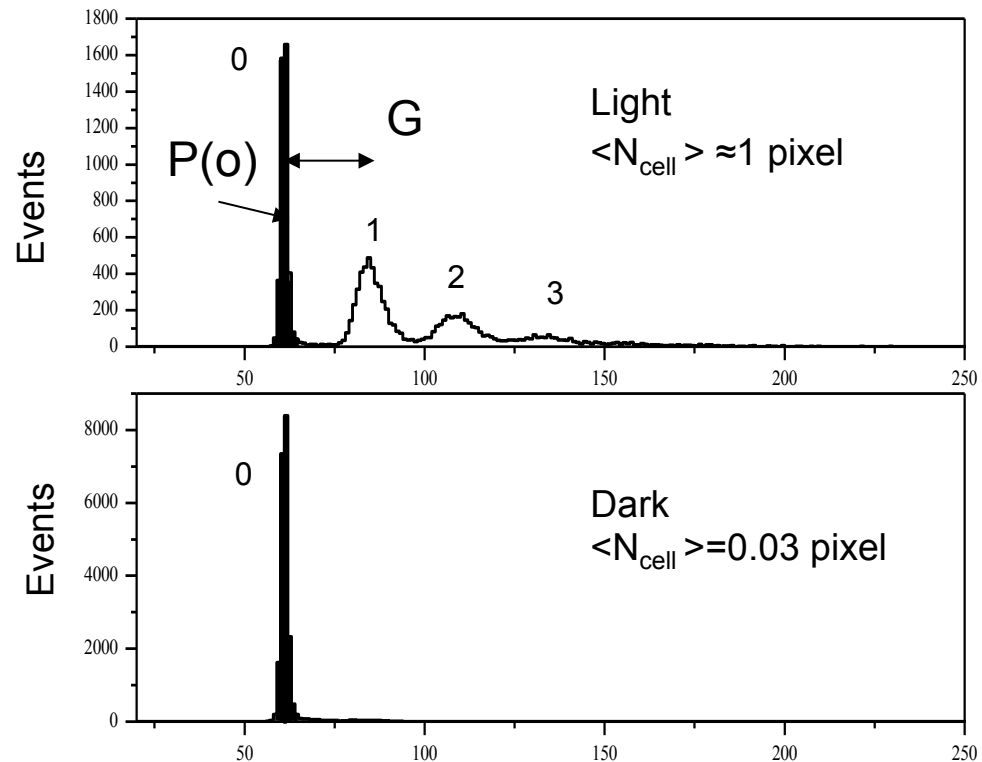
$\longrightarrow$  Correlated events

- Intrinsic timing jitter **SPTR**

(single pixel time resolution)

SiPM's single pixel spectra is very useful thing for precise measurements!

There are allow us to determine all main SiPM parameters.

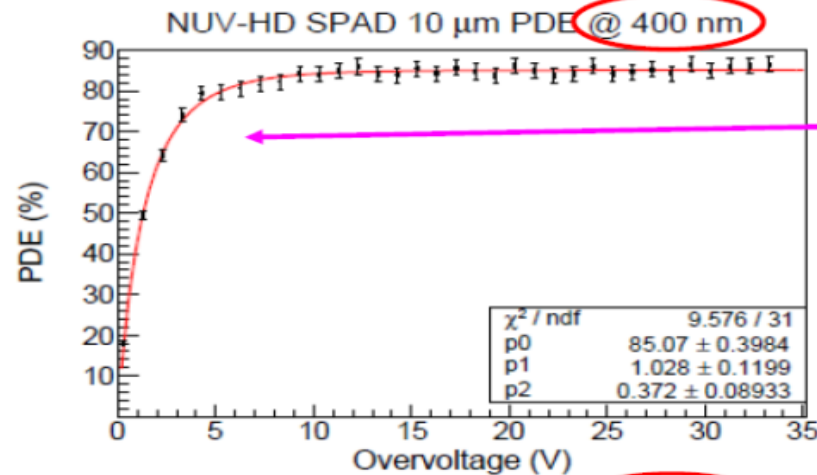


Quite important – **PDE**, **gain** and **xt** are measured independently

10

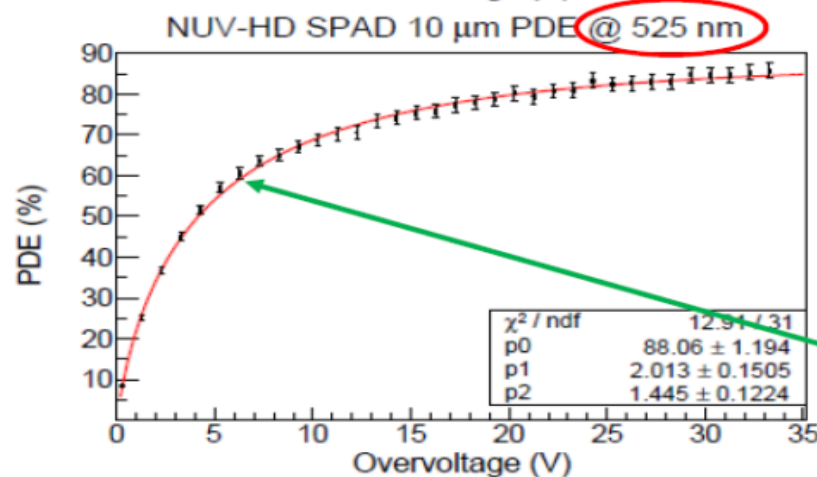
P.Eckert, et al. "Characterisation studies of silicon photomultipliers." Nucl. Instr. Meth. Phys. Res. A620 (2009), 217-226

# NUV-HD: QE\*Pt

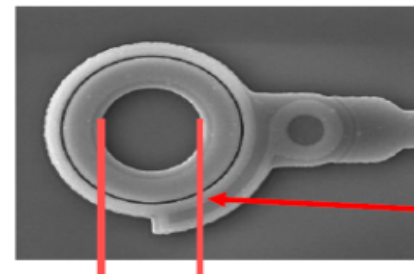


Fast increase with over-voltage:  
→ avalanche is initiated by electrons

Measured on a SPAD  
with 100% FF



Slower increase with over-voltage:  
→ avalanche is initiated by holes  
(and electrons)



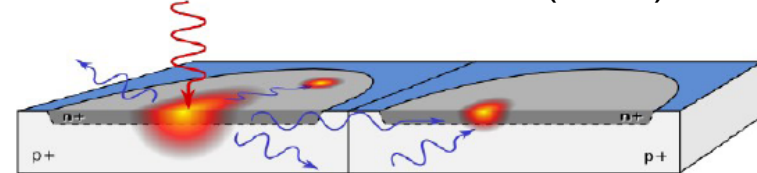
SPAD size is  
defined by metal  
opening which is  
within the high-field  
region

$\text{PDE} = f(\Delta V)$  we need to apply high overvoltage to reach high value of PDE  
Do we have problem here?



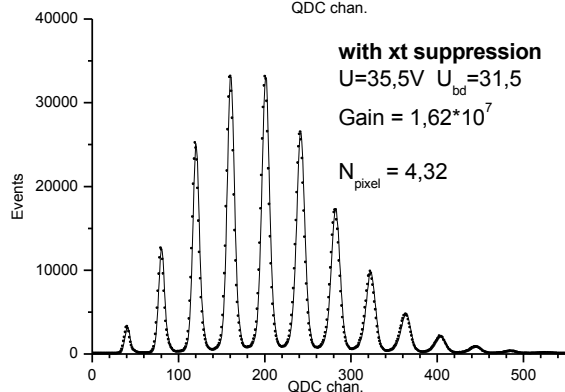
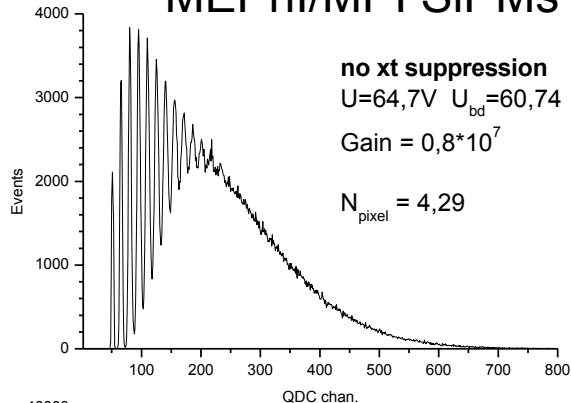
# Main SiPM's parameters. Crosstalk (XT)

A.Lacaita et al. IEEE TED(1993)



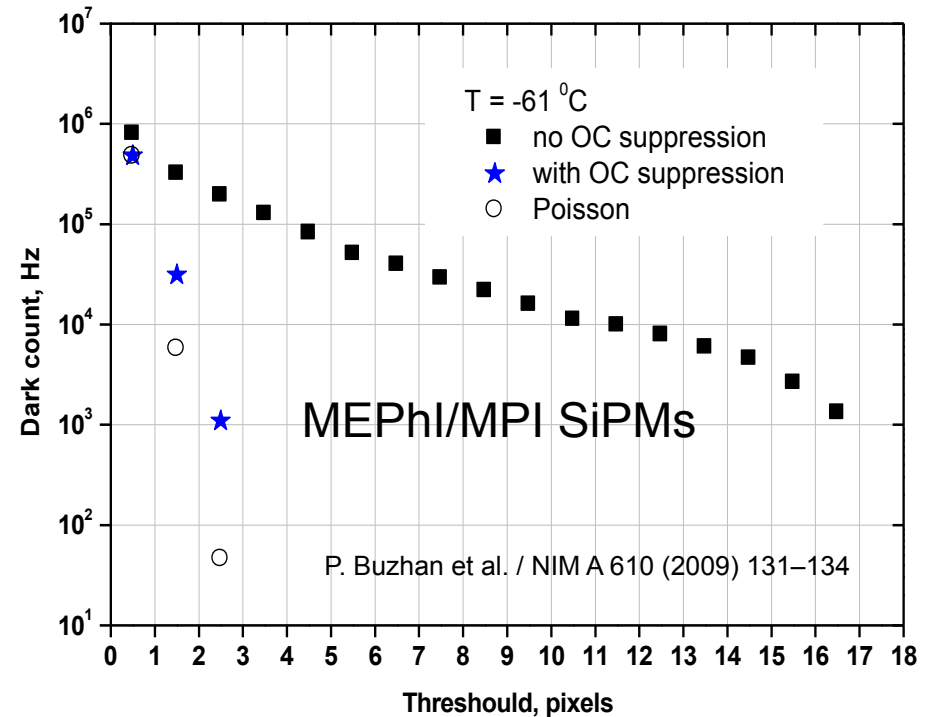
## Xt and light signal

### MEPhI/MPI SiPMs



Geiger discharge emits secondary photons

## Xt and dark rate

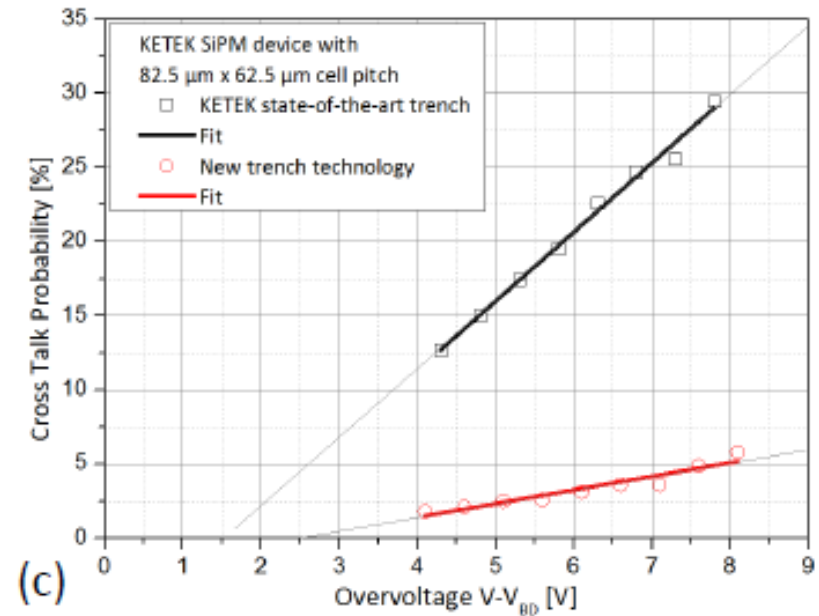
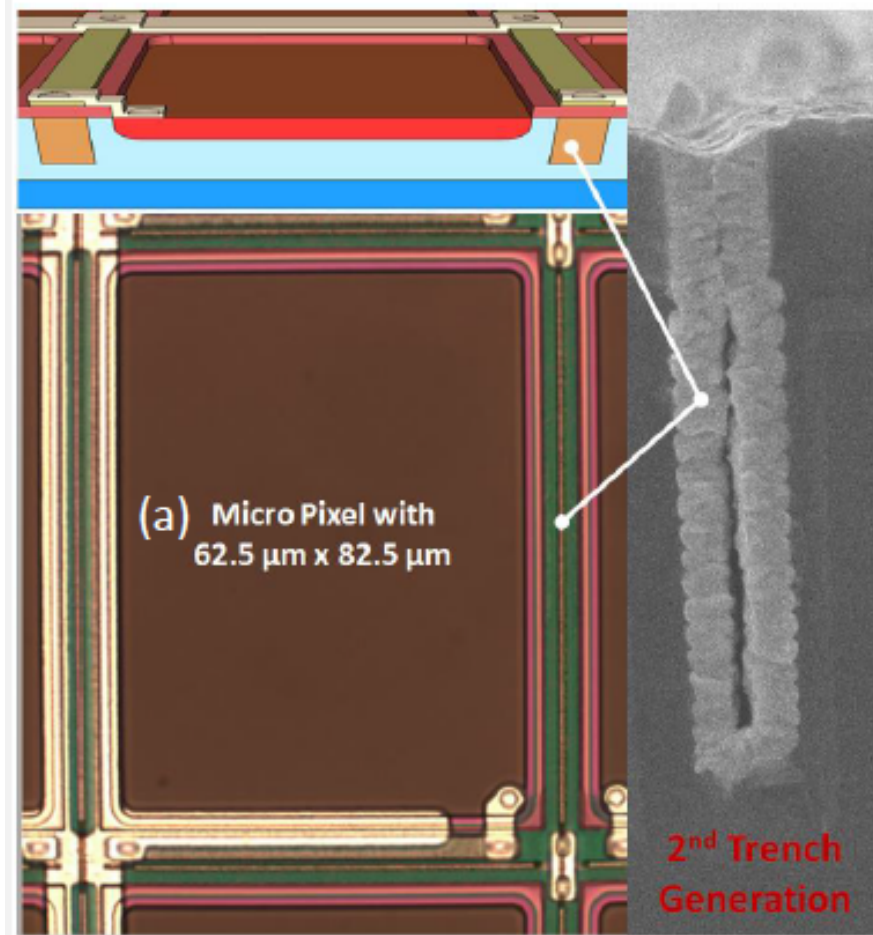


(IMAGING2010 Stockholm, Sweden June 8 – 11, 2010  
 B.Dolgoshein "Silicon Photomultiplier")

Main protection from crosstalk – optical trenches between the SiPM cells



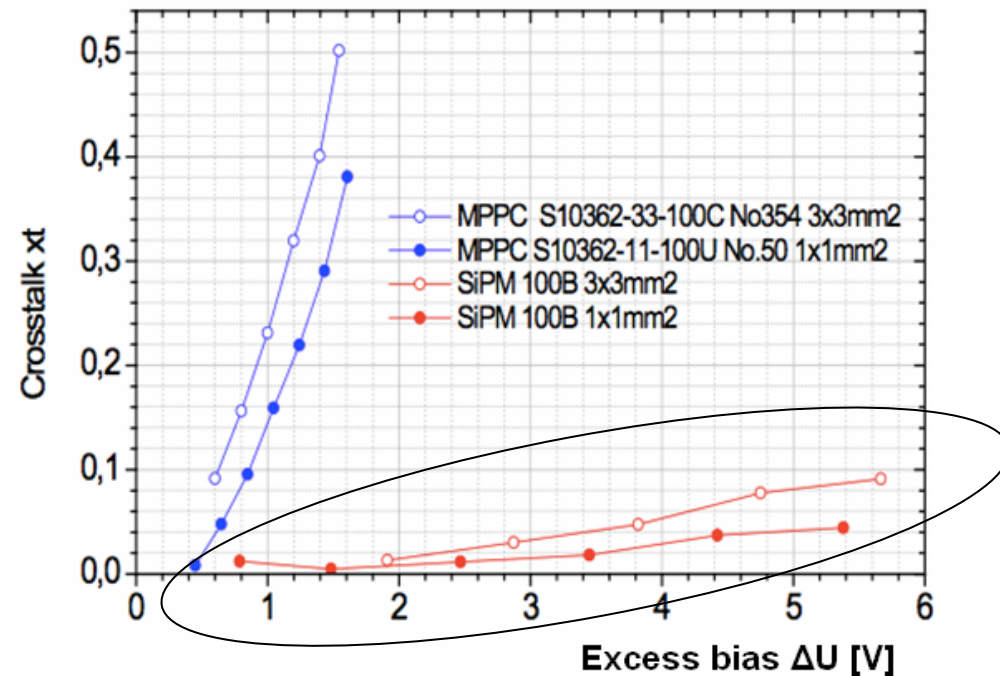
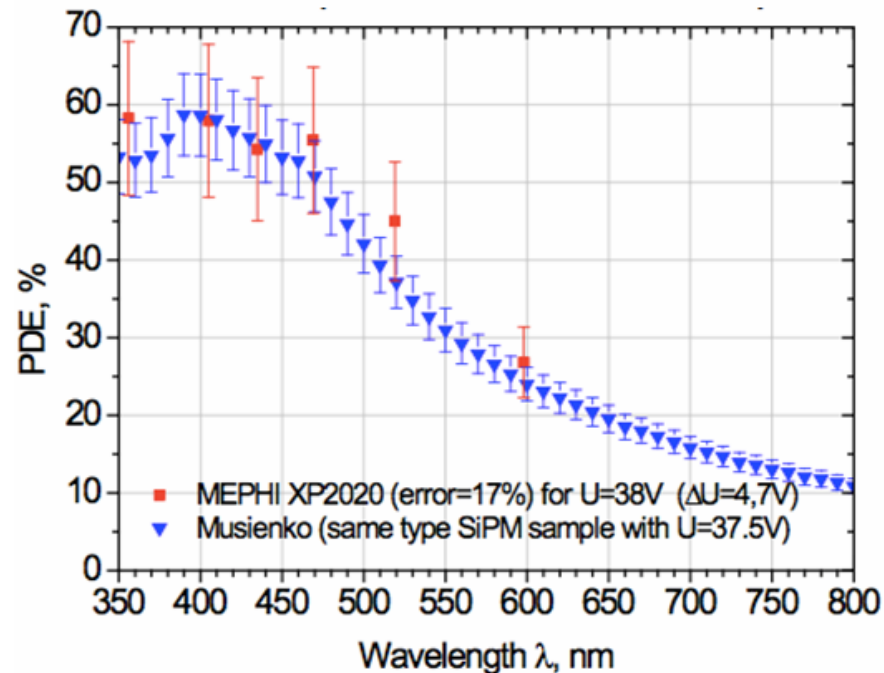
One needs to introduce opaque trenches in-between the SiPM pixels to suppress the optical crosstalk!



F.Wiest NDIP2014

MEPHI-MPI developed SiPMs (2010)

The First demonstration of PDE 60% and crosstalk 3% for 1x1 mm<sup>2</sup>



Elena Popova, MEPHI (NDIP 2011)

Special SiPM design with 4-fold crosstalk suppression



# PDE vs. XT

What is better –

- High PDE and high crosstalk?
- Low crosstalk and low PDE?

Of course **High PDE and low crosstalk!**

But you can find quantitative answer in Sergey Vinogradov's SiPM statistical analysis:

S. Vinogradov, Analytical models of probability distribution and excess noise factor of solid state photomultiplier signals with crosstalk, Nucl. Instruments Methods Phys. Res. Sect. A Accel. Spectrometers, Detect. Assoc. Equip. 695 (2012) 247–251. doi:10.1016/j.nima.2011.11.086.  
S. Vinogradov et al., Probability distribution and noise factor of solid state photomultiplier signals with cross-talk and afterpulsing, 2009 IEEE Nucl. Sci. Symp. Conf. Rec. (2009) 1496–1500. doi:10.1109/NSSMIC.2009.5402300.  
S. Vinogradov et al., Efficiency of Solid State Photomultipliers in Photon Number Resolution, IEEE Trans. Nucl. Sci. 58 (2011) 9–16. doi:10.1109/TNS.2010.2096474.

## Excess Noise Factor (ENF) as a measure of noisiness of a process



Ex.photon detection

1. Random input, random output,  $\varepsilon = \text{sigma}/\text{Mean}$

$$\varepsilon_{out} = \sqrt{ENF} * \varepsilon_{in}$$

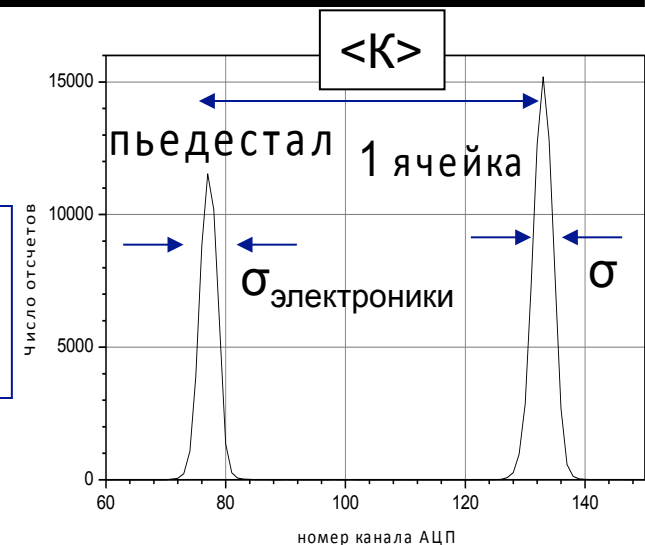
2. Fixed input, random output  
Example – single photon response K (gain)

$$ENF_{gain} = \frac{\langle K^2 \rangle}{\langle K \rangle^2}$$



$$ENF_{gain} = 1 + \frac{\sigma_1^2}{\langle K \rangle^2}$$

$$\sigma_1 = \sqrt{\sigma^2 - \sigma_{electronics}^2}$$

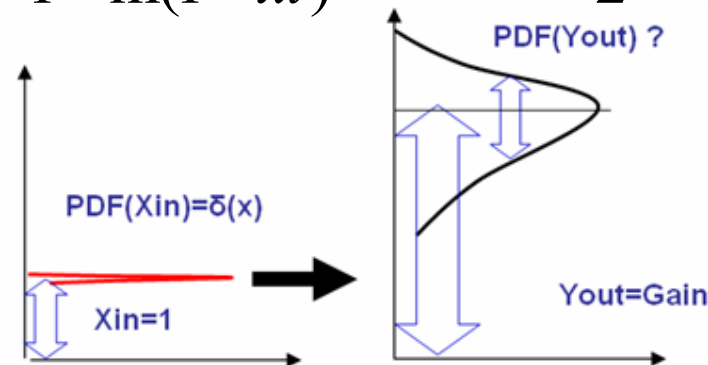


## □ Crosstalk

$$ENF_{xt} = \frac{1}{1 - \ln(1 - xt)} \approx 1 + xt + \frac{3}{2}xt^2 + \dots$$

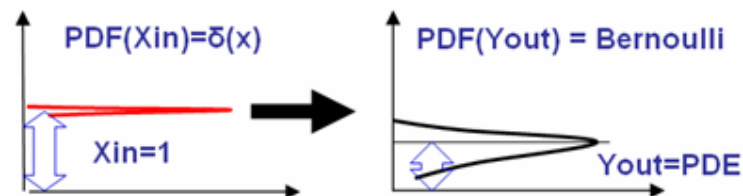
## □ Multiplication

$$ENF_{gain} = 1 + \frac{\sigma_{gain}^2}{Gain^2}$$



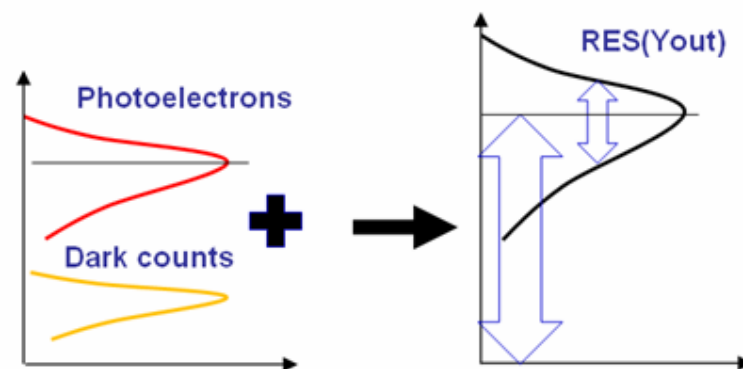
## □ Photon detection

$$ENF_{pde} = 1 + \frac{PDE \cdot (1 - PDE)}{PDE^2} = \frac{1}{PDE}$$



## □ Dark counts

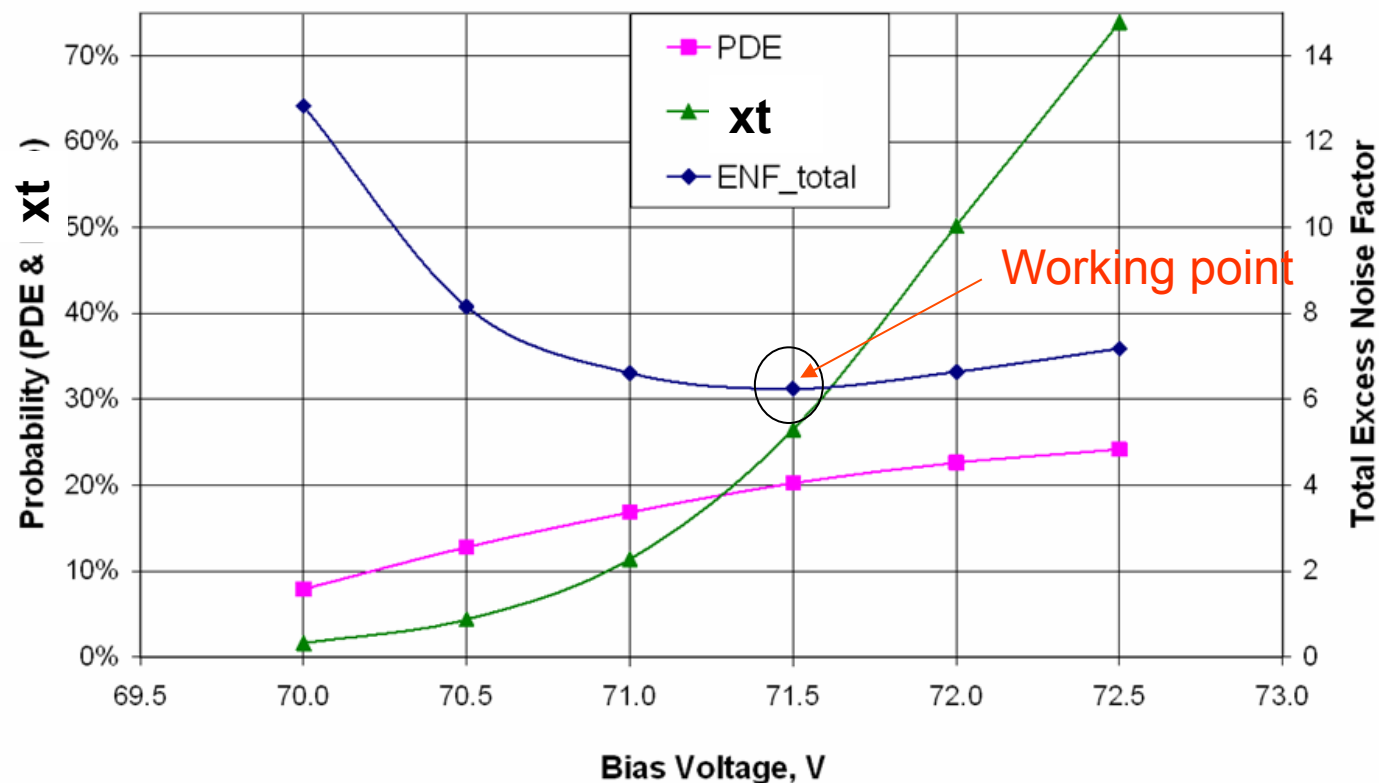
$$ENF_{dcr} = 1 + \frac{DCR \cdot t}{N_{pe}}$$



## ◆ Total ENF for a sequence of specific processes is

$$RES(Y_{out}) = RES(X_{in}) \cdot \sqrt{ENF_{total}} = RES(X_{in}) \cdot \sqrt{ENF_{process\ 1} \cdot ENF_{process\ 2} \cdots}$$

### PDE & XT overvoltage trade-off



Total ENF based on PDE and P\_dup relation (6) in detection of 60 ps 700 photon pulses in 100 ns gate by 1 mm MPPC 1600 pixels (vendor spec. bias 71.2V). S. Vinogradov et al., IEEE NSS/MIC 2009.



# Main SiPM producers now

- On Semiconductor (acquires SensL Technologies Ltd.) - worldwide
- Broadcom (license of FBK technology)-worldwide
- Hamamatsu Photonics HPK, Japan
- FBK, Italy
- KETEK GmbH, Germany
- NDL Novel Device Laboratory, China

# SiPM Zoo at the time being

The widest range of SiPMs for different applications are offered today by FBK and Hamamatsu

let's consider what types of SiPMs (MPPCs) exist on the example of the Hamamatsu company

## 2 Ways of development



### Industrial

- High volume
- Low cost
- Commercial profit



### Scientific

- High performance
- Unique requirements
- Driver for improving of technology





# Industrial applications

## New MPPC Series

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5

### <MPPC Series>

### <Application>

**S1336x series**  
(UV-VIS : General)

- General use

**S1416x series**  
(UV-VIS: Scintillation)

- PET  
(Positron Emission Tomography)  
- Radiation monitor

**S1442x series**  
(VIS-NIR: Peak shifted)

- Laser microscope  
- Flow cytometry  
- Bio-medical

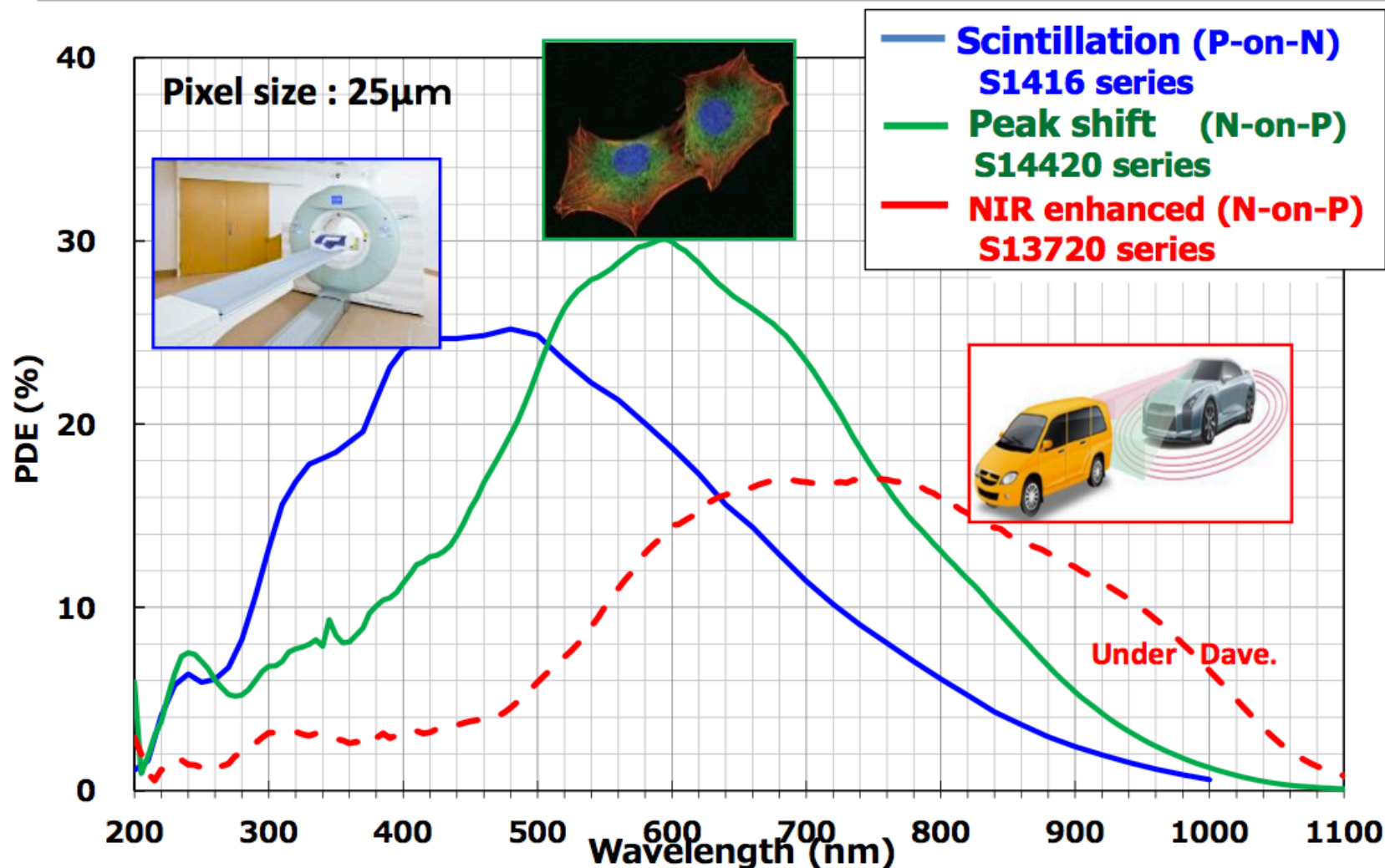
**S1372x series**  
(NIR: NIR-enhanced)

- LiDAR  
(Light Detection and Ranging)

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# MPPC Series for Industrial applications

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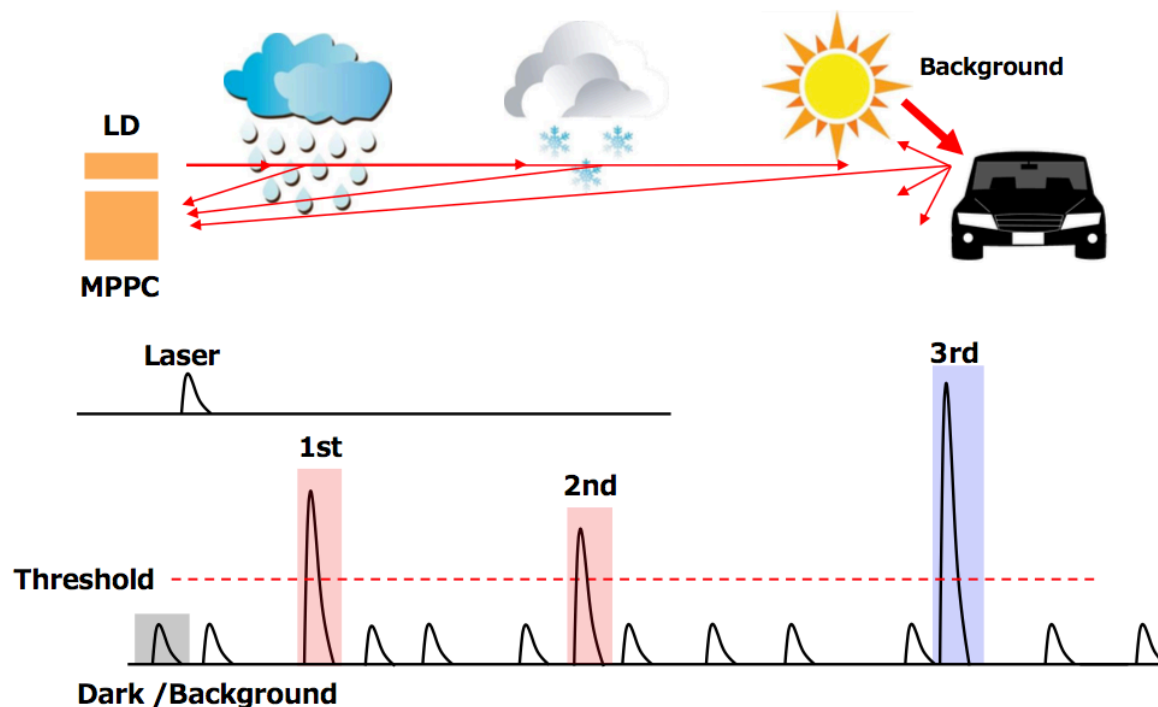


# LiDAR : Light Detection and Ranging

## Optical signal in LiDAR

Signal returned from the target is very weak,  
and the background light is high

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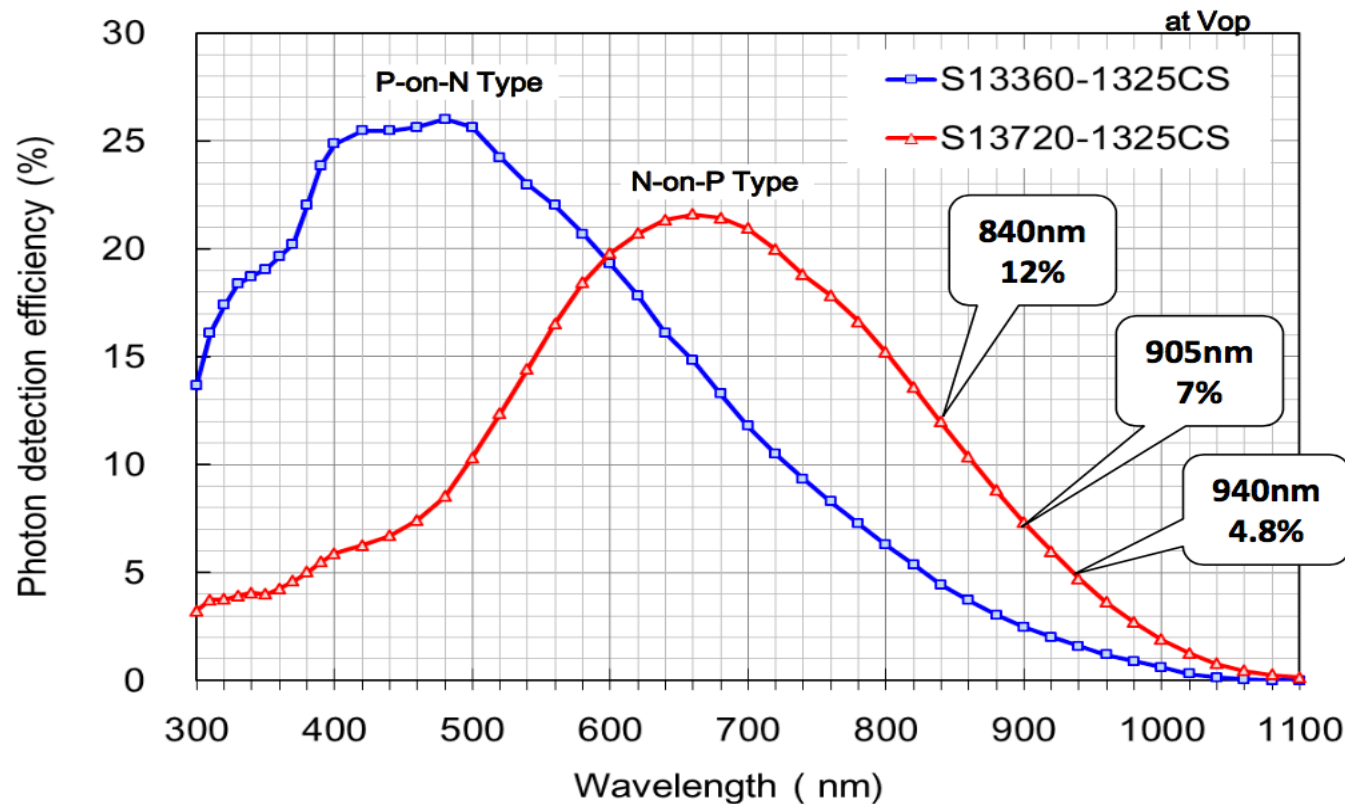
Lidar – area of a new SiPM development

Light wavelength 800 nm ~ 1.06  $\mu\text{m}$  – Silicon

Longer wavelength – other non-silicon materials



## Photon Detection Efficiency

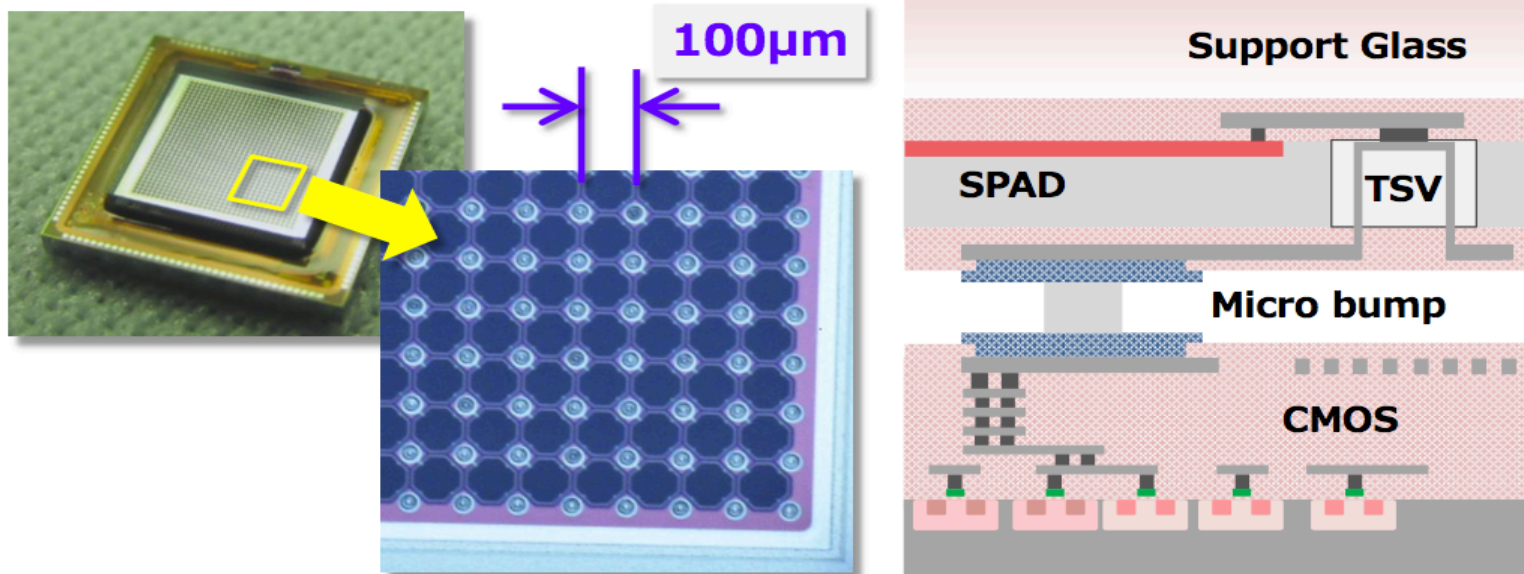


New development in many companies in order to increase sensitivity to IR light  
FBK PDE(905)=12% 35 micron pitch  
KETEK PDE(905)=20% 15 micron pitch

# To Solid state LiDAR (Flash LiDAR)

## Hybrid photon counting image sensor

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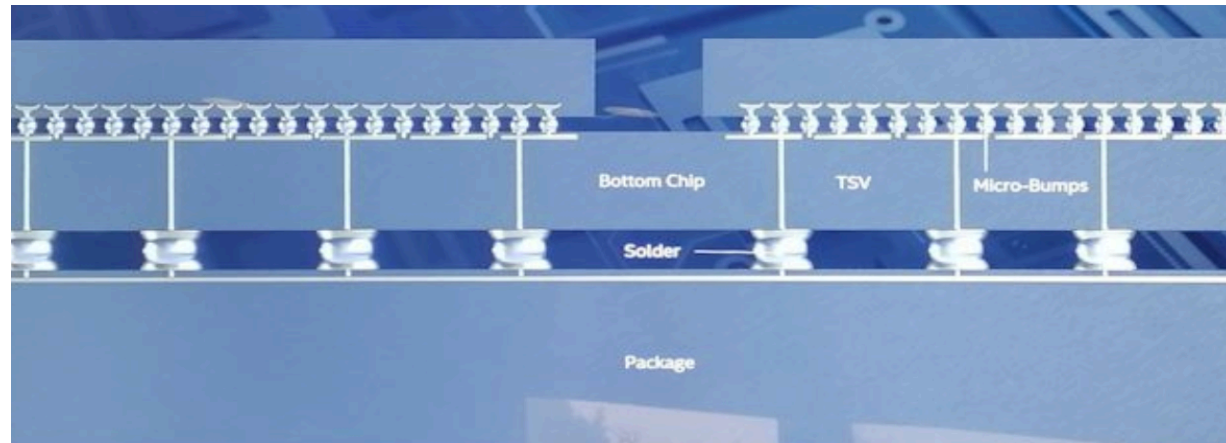


- **Sensor and ASIC 2 layer structure**
- **High aperture ratio >50%**
- **100 μm pitch TSV**

Sectional view

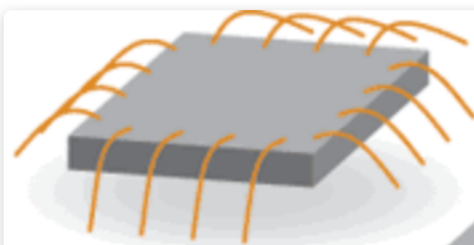
A 3D Flash LIDAR transfers distance and black-and-white video via a single laser pulse with each data frame, where they are captured by a Focal Plane Array of smart pixels.

TSV – **through-silicon via** is a vertical electrical connection that passes completely through a silicon wafer or die. TSVs are high performance interconnect techniques used as an alternative to wire-bond and flip chips to create 3D packages and 3D integrated circuits.

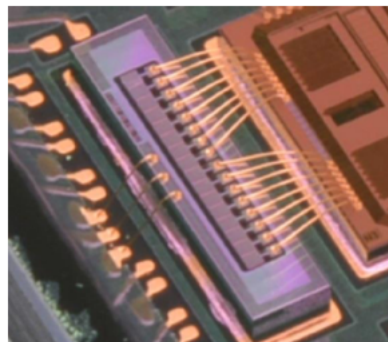


The flip chip ( "Reversible assembly") is a method of packaging and interconnection technology for contacting of bare semiconductor chips (Bare die) by means of bump contact - so-called "bumps"

Wire bonding

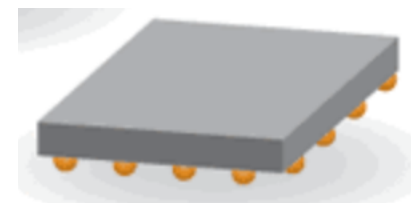


E.Popova, MEPhI



SiPM mini-school, Ringberg 2019

Flip-chip

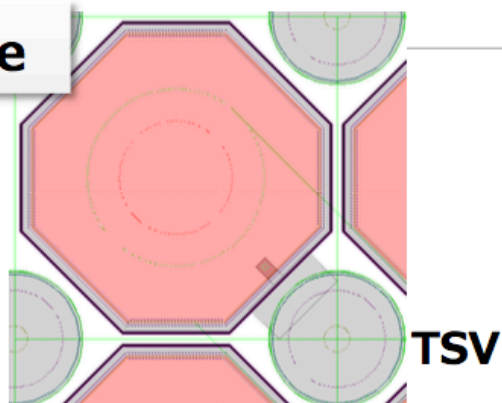




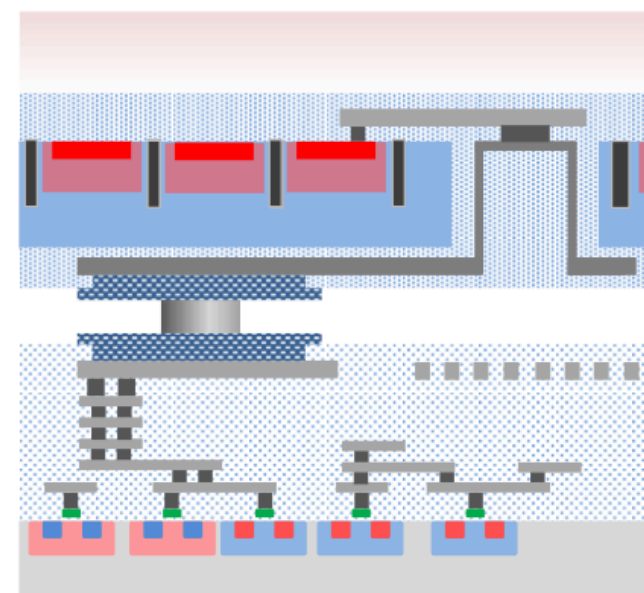
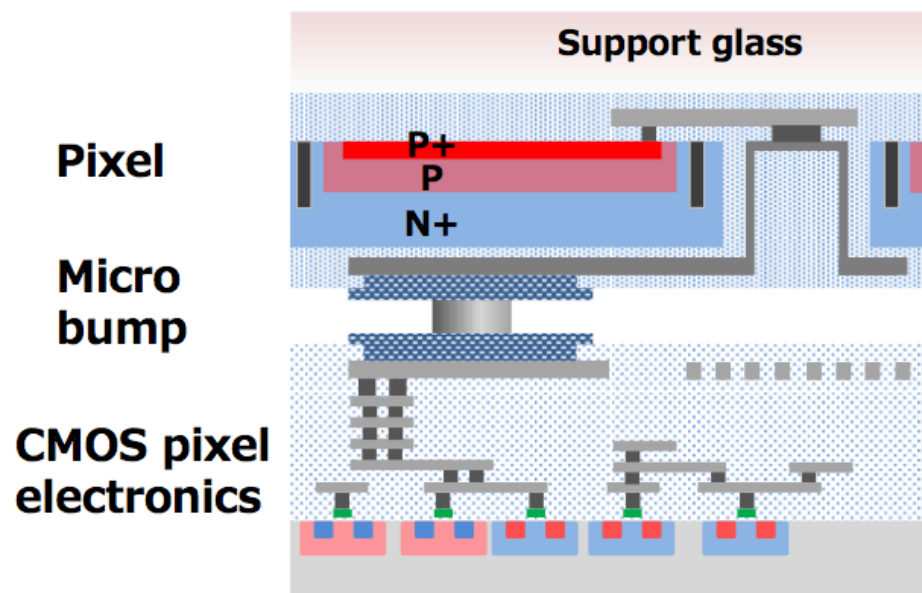
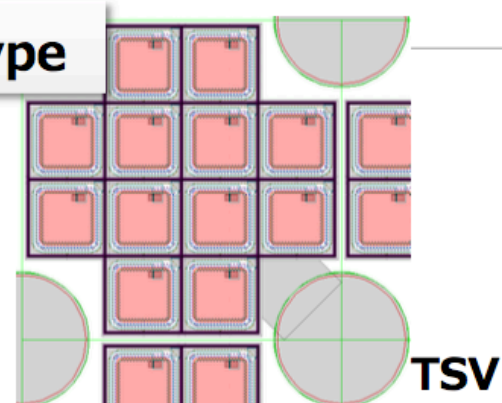


# Si SPAD/Front illuminated MPPC

**SPPC type**

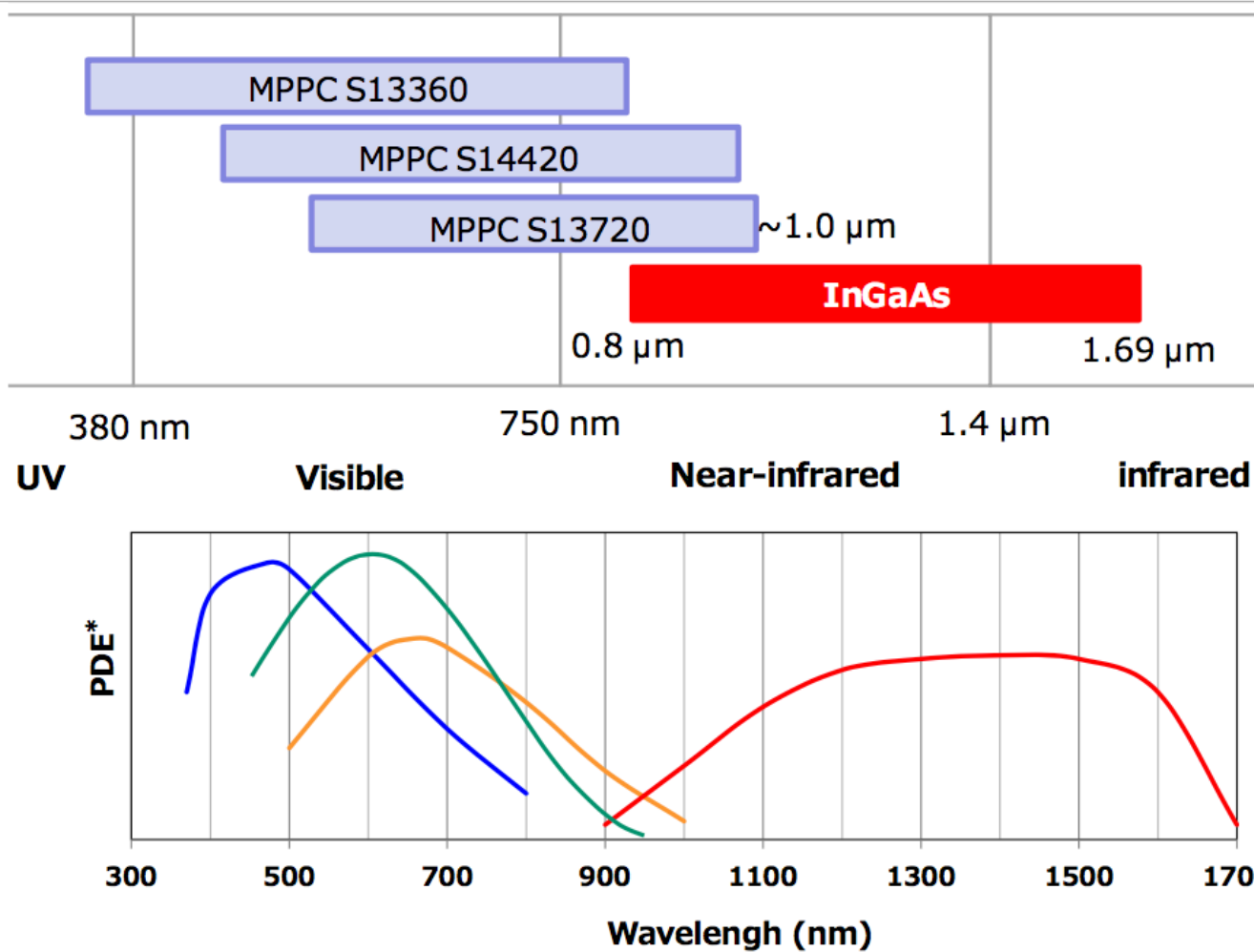


**MPPC type**





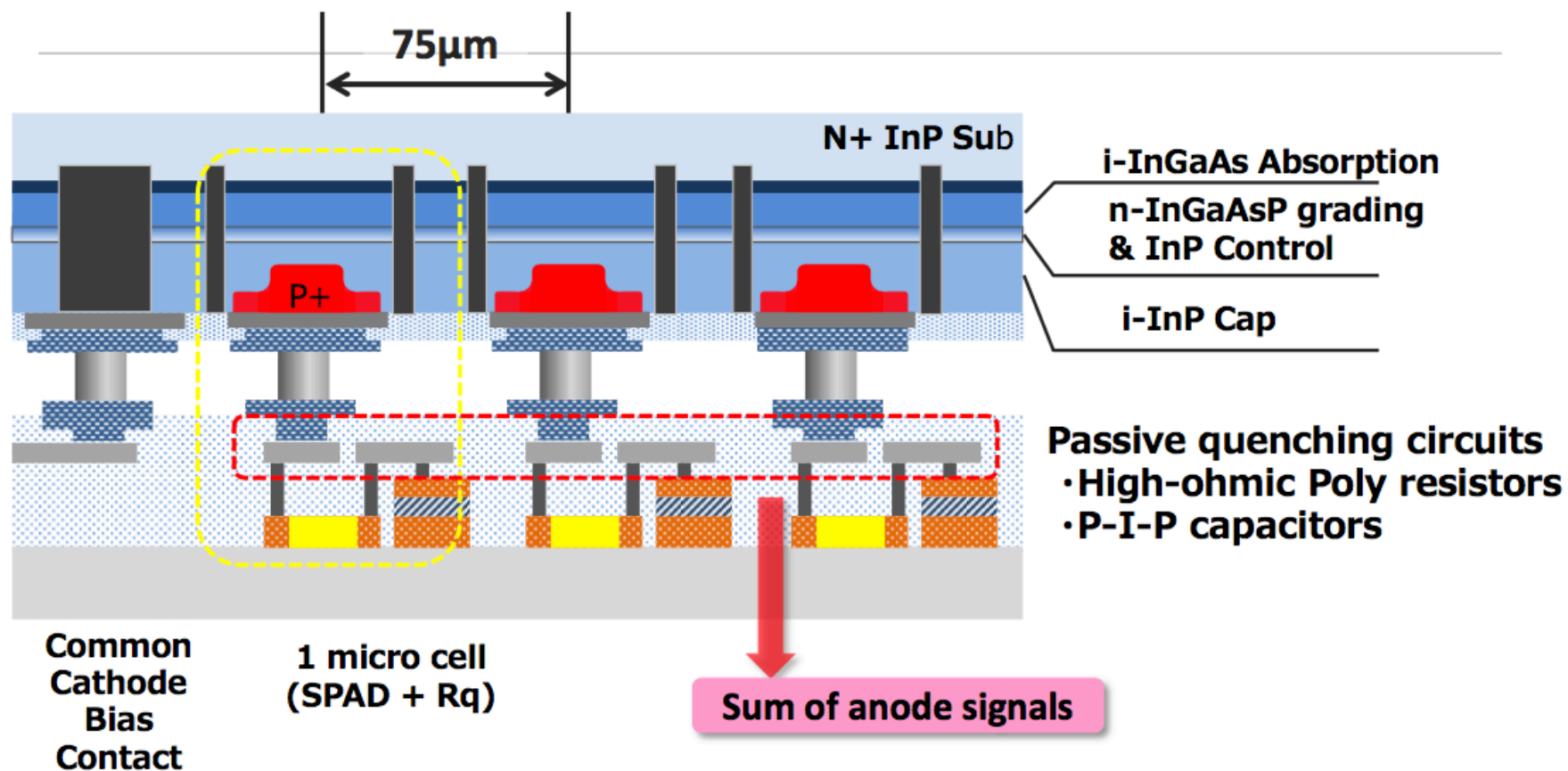
## Si and InGaAs MPPC



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# InGaAs MPPC Structure

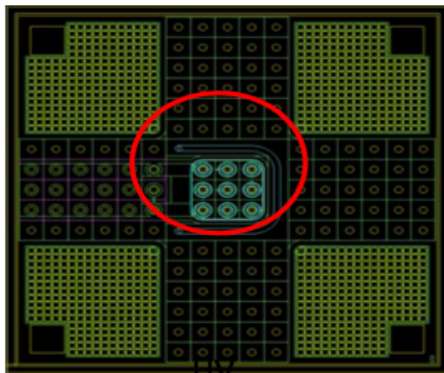


- ❑ This 1<sup>st</sup> trial design is 3×3 pixel configuration.
- ❑ Anode signals from each micro cell are summed and read out as a current signal.

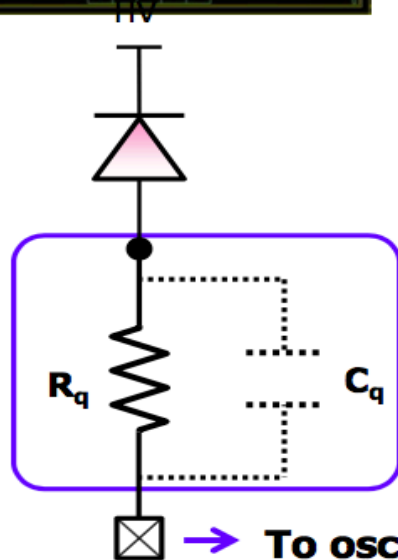


## InGaAs-MPPC Development

3X3 InGaAs chip

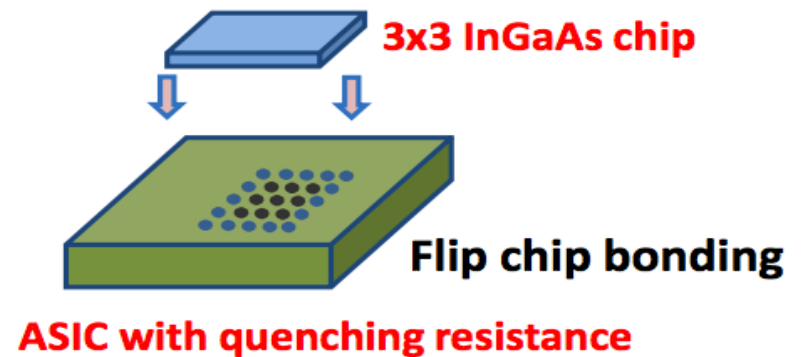
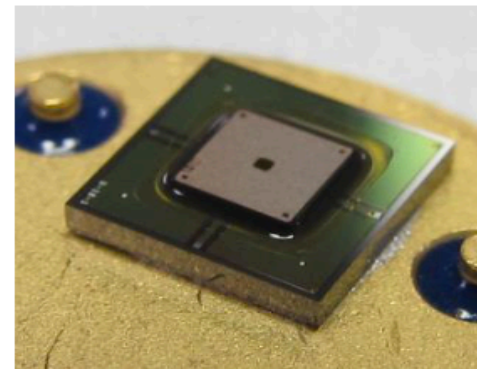


CMOS



→ To oscilloscope

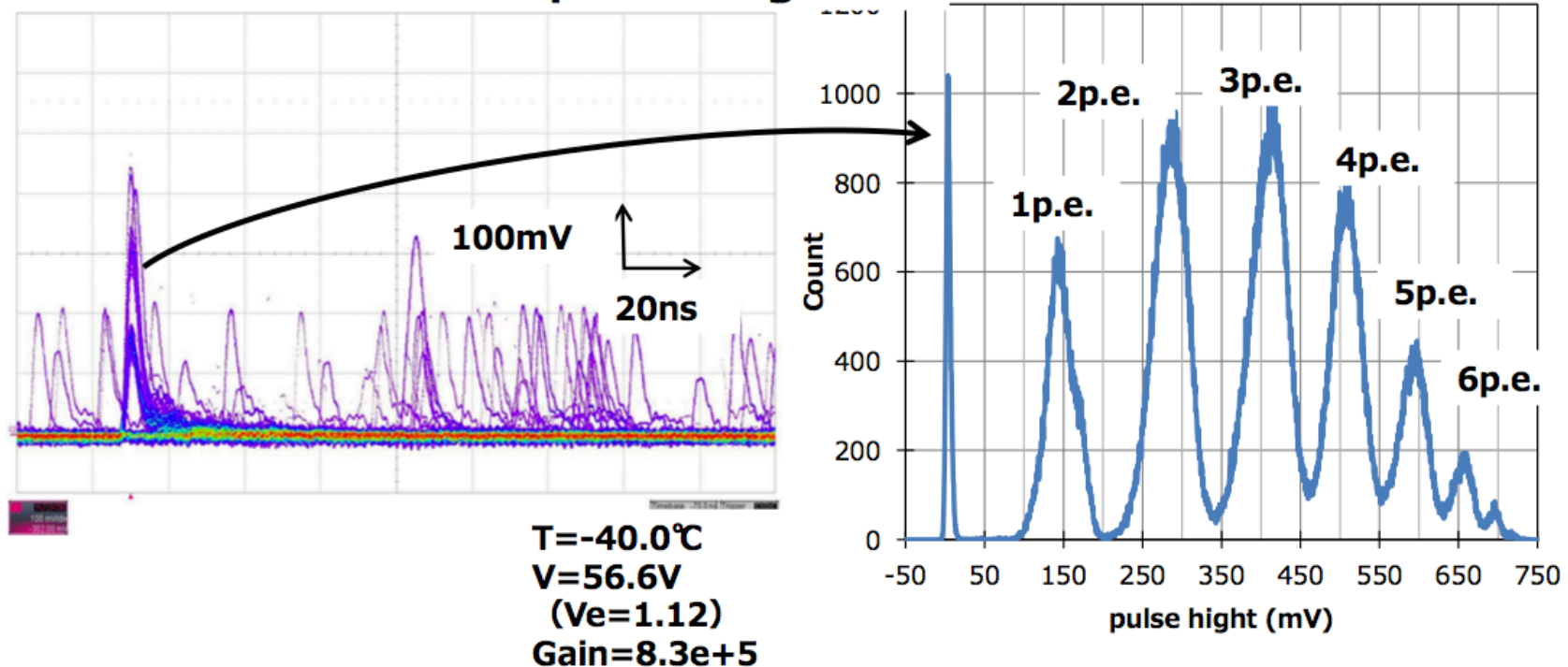
**Hybrid Type**  
(MPPC chip and ASIC with In bump)





## InGaAs-MPPC(Waveform of 3x3 pixel device)

### Count numbers of pulse height



**We could confirm the basic behavior as MPPC.**



## New MPPC Series for Scientific Application

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### <MPPC Series>

### <Application>

**S1337x series**  
(VUV-MPPC)

- Liq. Xe / Ar scintillation  
measurement

**S1452x series**  
(CTA-MPPC)

1

- CTA  
(Cherenkov Telescope Array)

**S1416x series**  
(Small microcell: HDR-MPPC)

- Calorie meter  
- High Dynamic Range  
measurement

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**Dark matter research**

## **VUV MPPC**

- **High sensitivity for VUV**
- **Low RI**

**This presentation is an intermediate, VUV sensitivity increase and new low RI package development are on going**

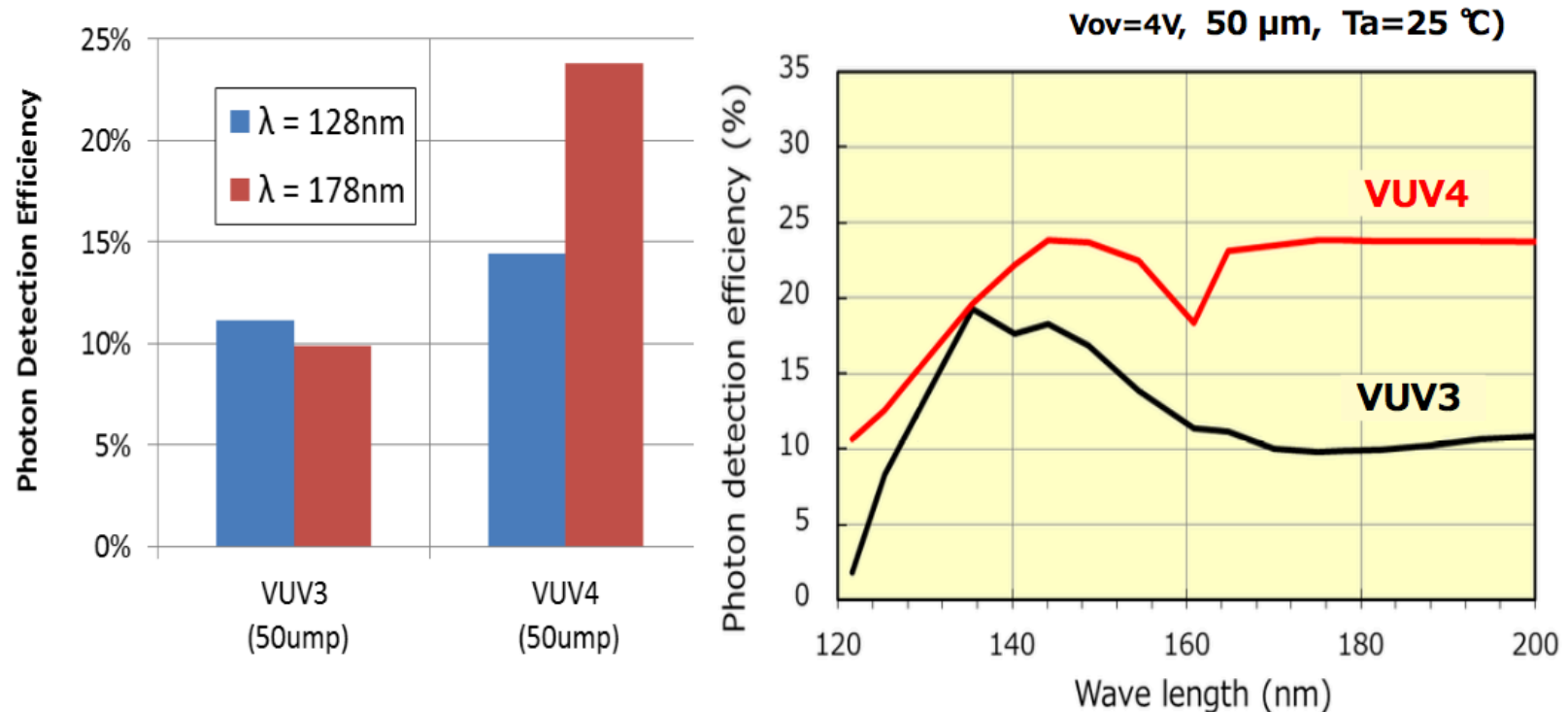
**HAMAMATSU PHOTONICS K.K.**

## MPPC : VUV Detection

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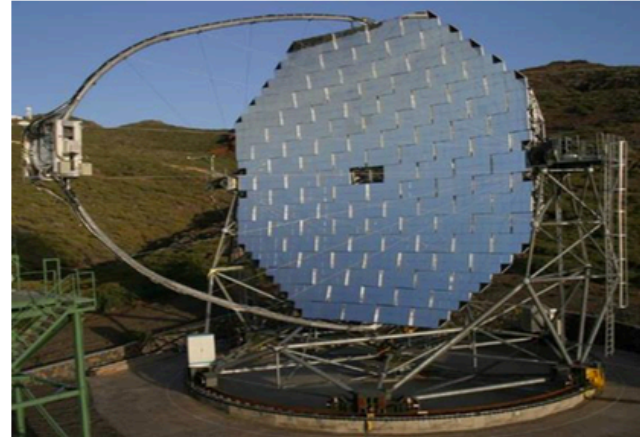
For physics experiments using LXe or LAr scintillator Liquid xenon (LXe) and liquid-argon (LAr) is used as scintillator. Their peak spectra are in VUV region and their temperatures are cryogenic.

### ➤ Improvement for VUV sensitivity (VUV4)



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## **MPPC for Cherenkov Telescope**

- **Higher PDE**
- **Lower Crosstalk**

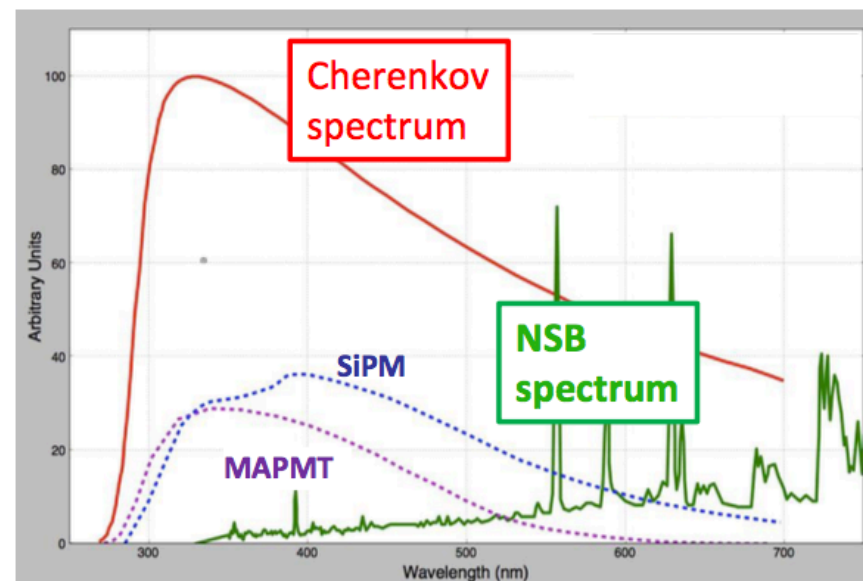


# MPPC for Cherenkov Telescope Array

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## Required Properties

- **High PDE @350nm**.....High F.F & large Pixel
- **Large sensitive area**.....Bigger than 6mm<sup>2</sup> and small dead space
- **Less visible sensitivity**.....Not so sensitive to NSB
- **High Gain**
- **Low cross talk**
- **Low dark count**

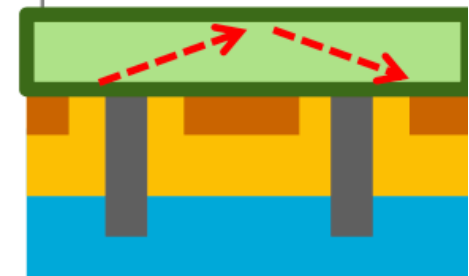
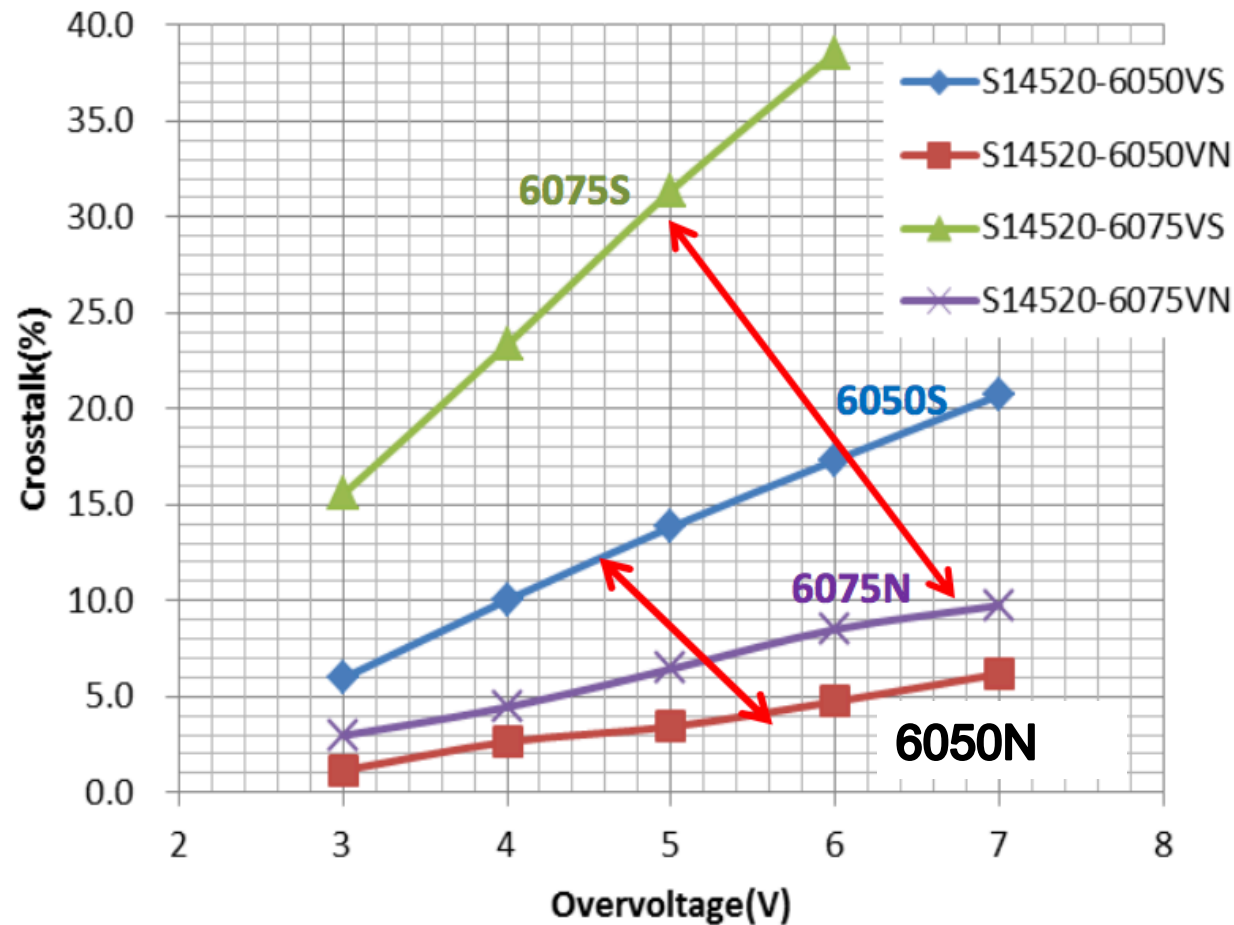


NSB: Night sky background



## Crosstalk - Coating vs Without Coating -

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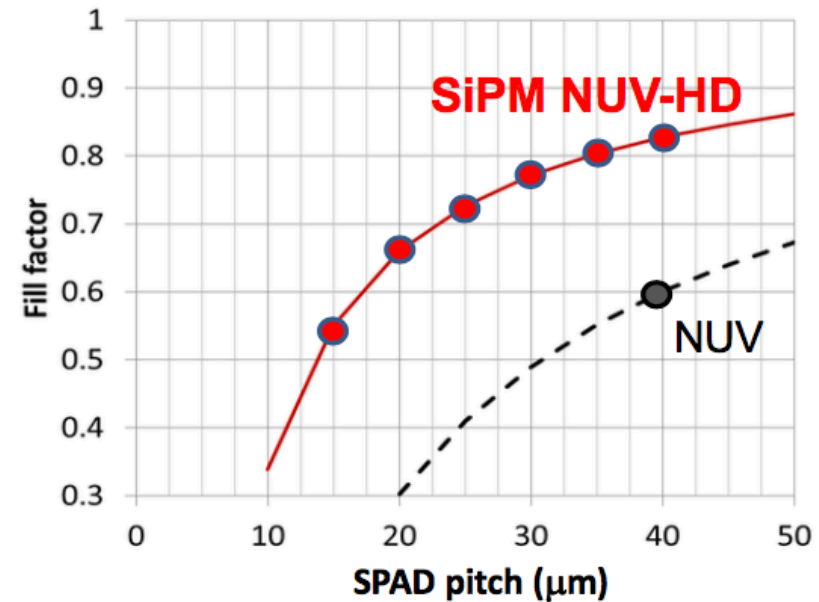
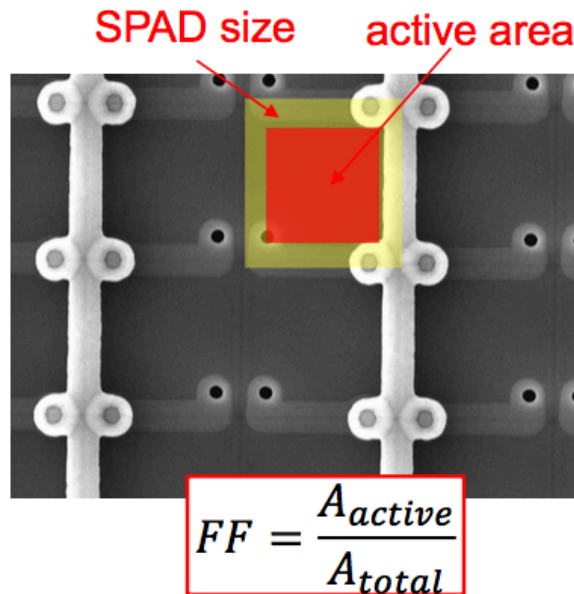
**VS (Mold Type)**



**VN (Without Coating)**

Crosstalk depends on SiPM area and protective coating!  
No coating – less crosstalk

## NUV-HD: Fill Factor



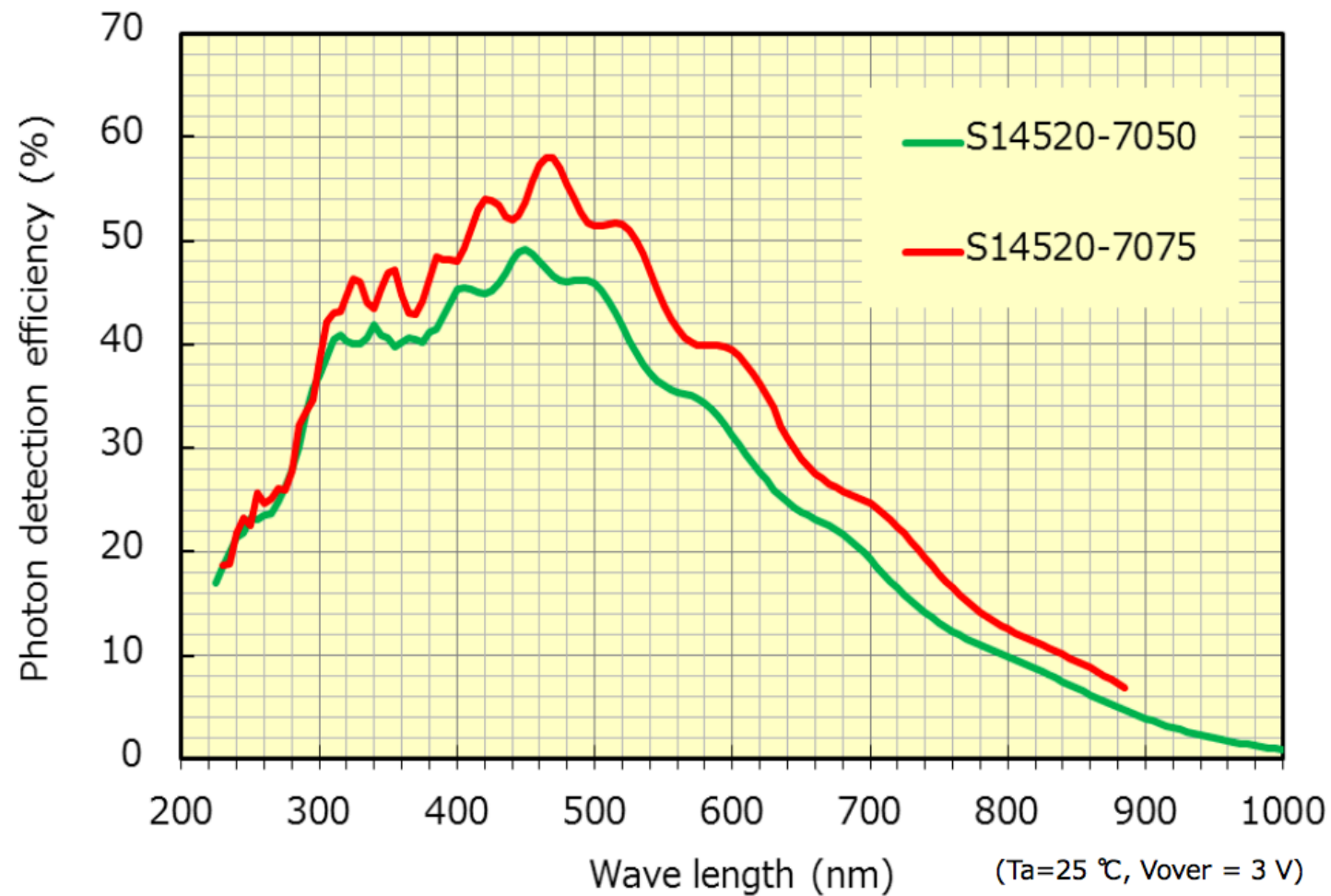
SPAD Pitch	15 μm	20 μm	25 μm	30 μm	35 μm	40 μm
Fill Factor (%)	55	66	73	77	81	83
SPAD/mm <sup>2</sup>	4444	2500	1600	1111	816	625

High Dynamic Range (15 μm to 30 μm)

High PDE (35 μm to 40 μm)

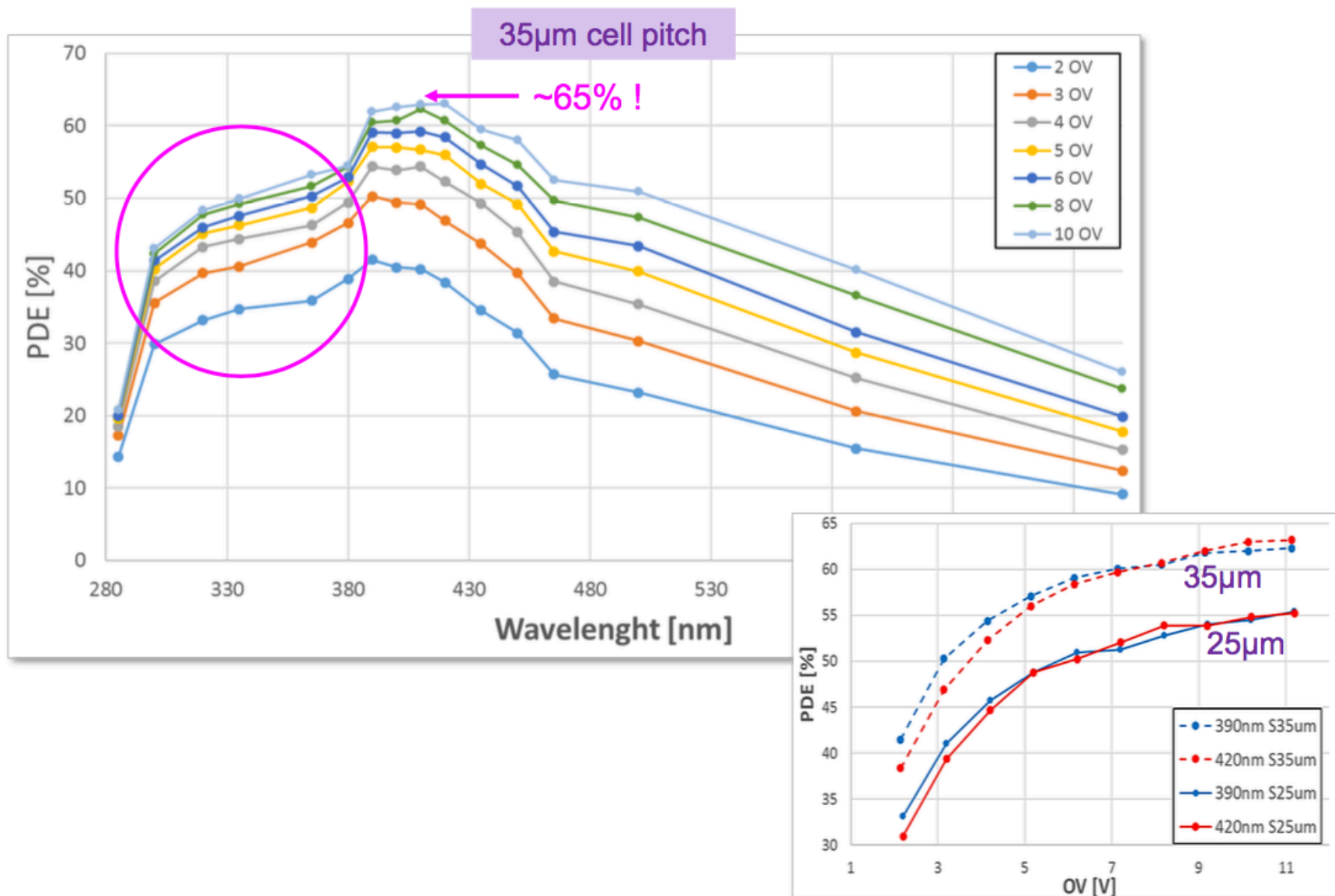
# PDE

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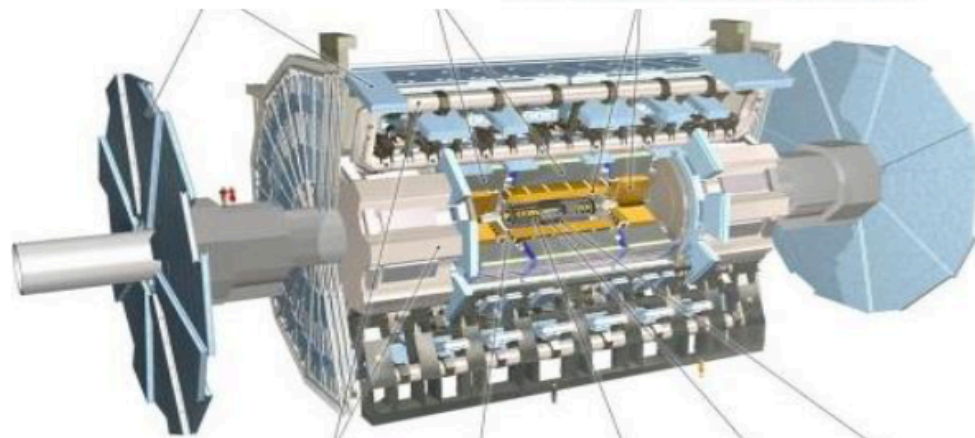
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# Photon detection efficiency



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## **Small Pixel size MPPC**

- **High dynamic range**
- **Radiation hardness**

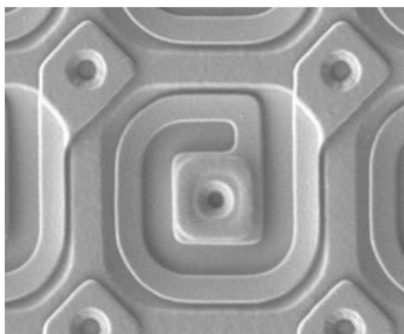
HAMAMATSU PHOTONICS K.K.

# Very tiny pixels 10 micron

Old without trenches

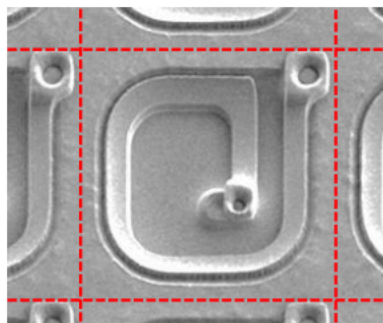
● Fill factor: 33%

10  $\mu\text{m}$

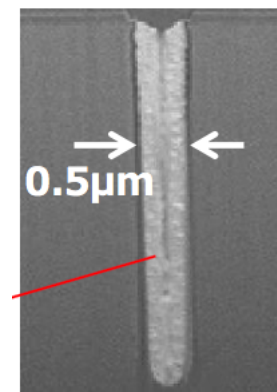


New with trenches

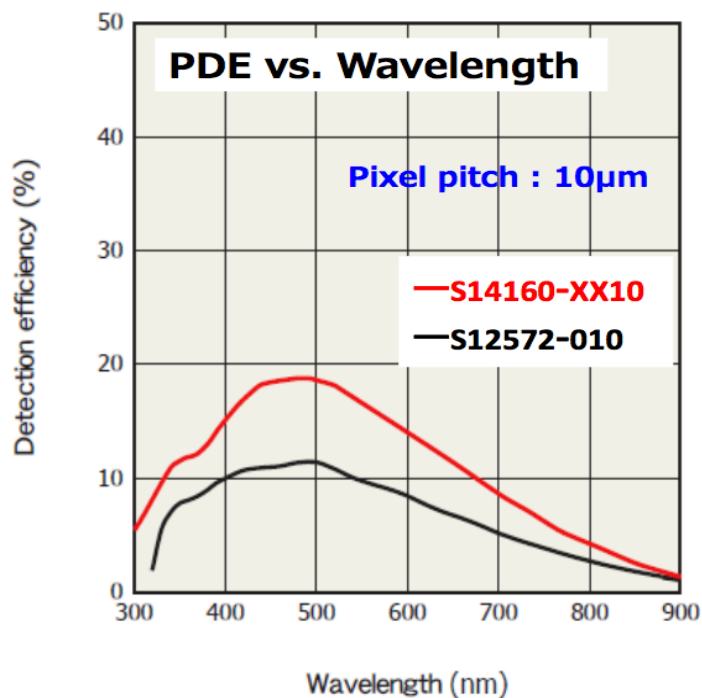
● Fill factor: 31%



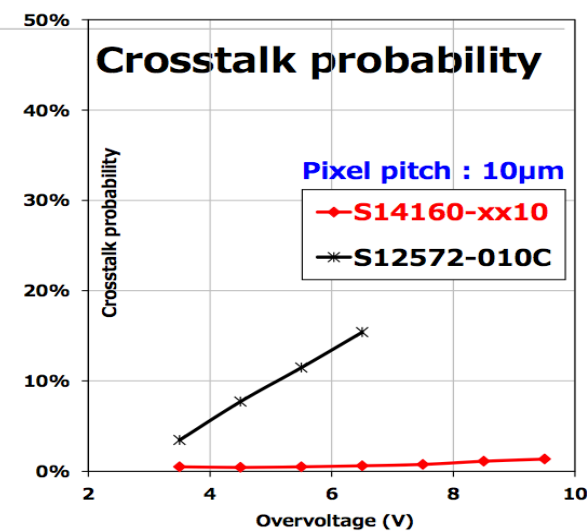
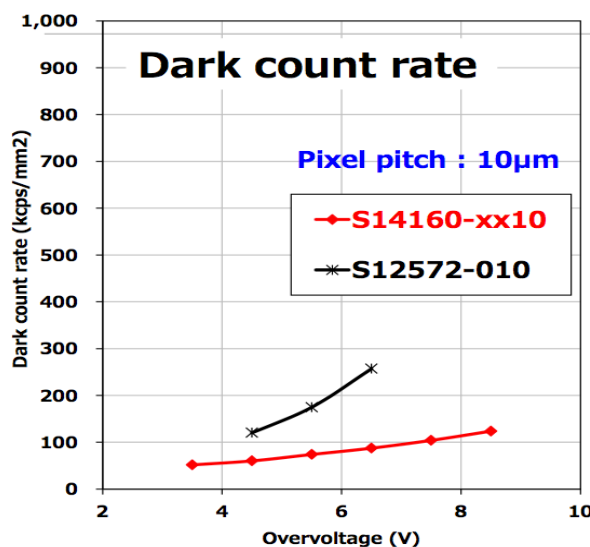
trench



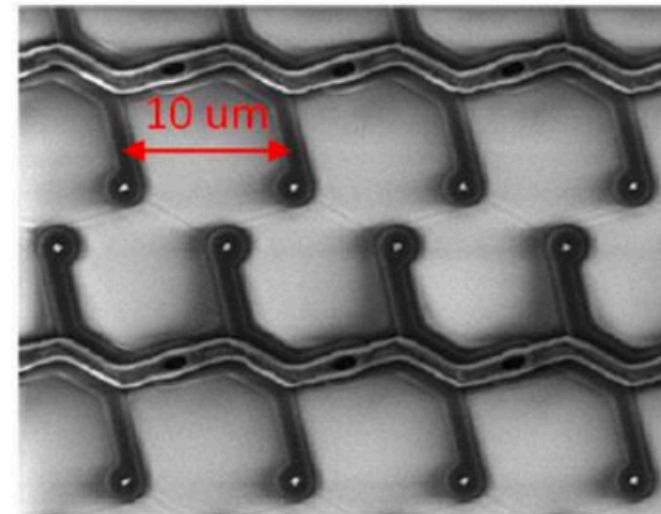
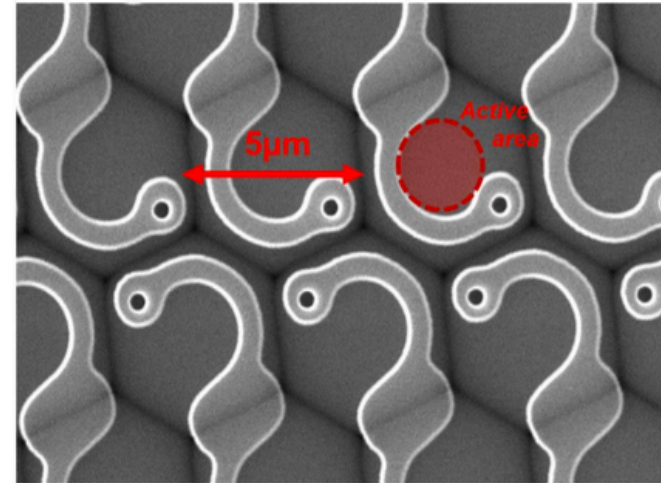
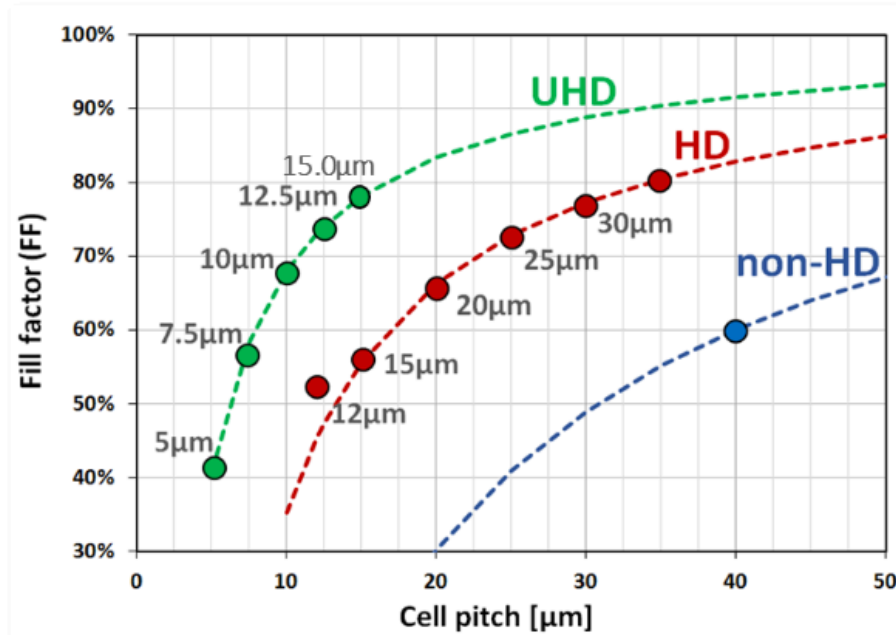
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## Dark count & Crosstalk



# HD and UHD technologies

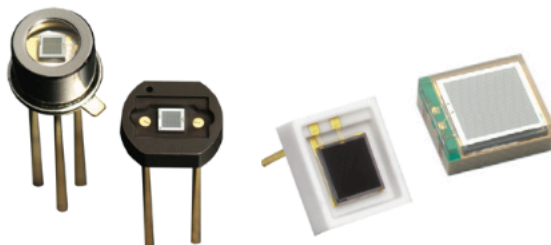

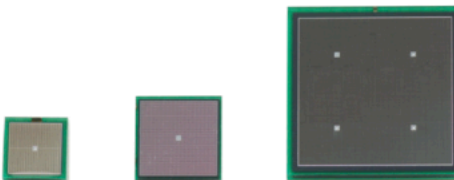
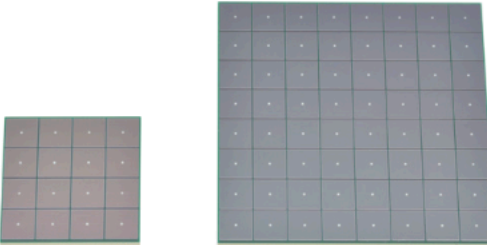


## RGB-UHD

cell size ( $\mu\text{m}$ )	cells/mm <sup>2</sup>
12	7400
10	11550
7.5	20530
5	46190

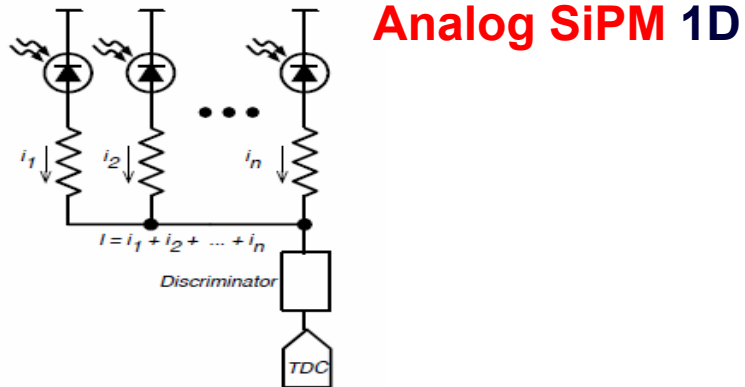


# Packaging

	
<b>Uncooled Single Element</b>	<b>TE-Cooled Single Element</b>
	
<b>Tile-able Single Element</b>	<b>Preconfigured Array</b>

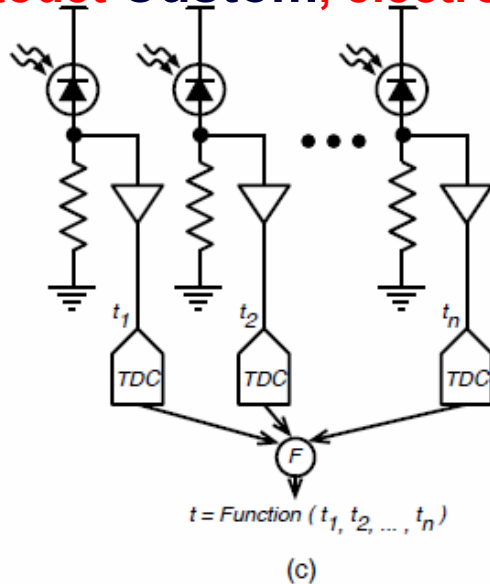
## Trends for further SiPM development

### Conventional SiPM, custom technology

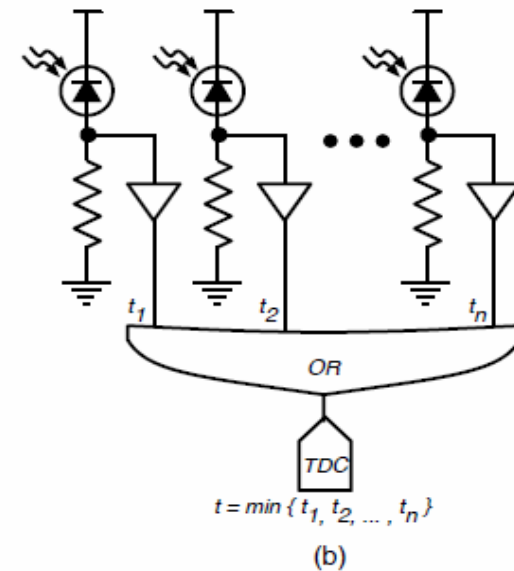


### Ideal multidigital SiPM, 3D integration

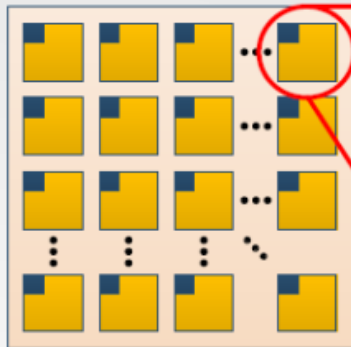
### Photodet Custom, electronics CMOS



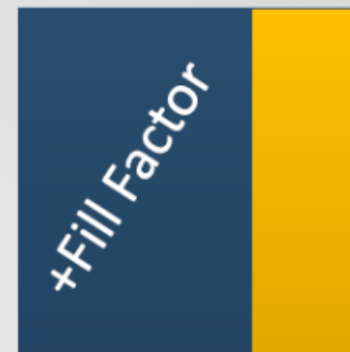
### Digital SiPM (Philips) 2D CMOS (modified) technology Photodet & electronics



## Digital SiPM: Trade off and Solution



OR

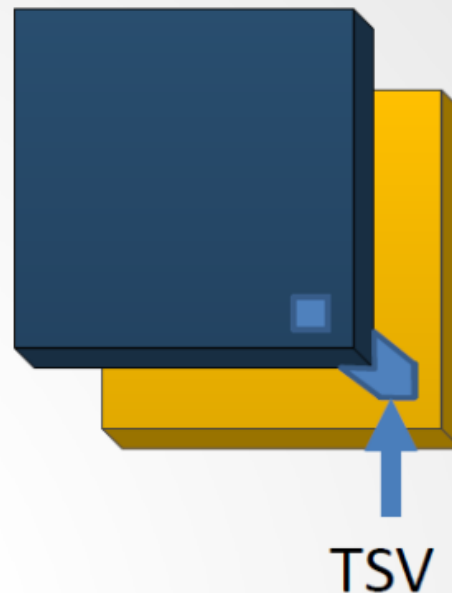


= SPAD



= Readout Circuit

IDEALLY:

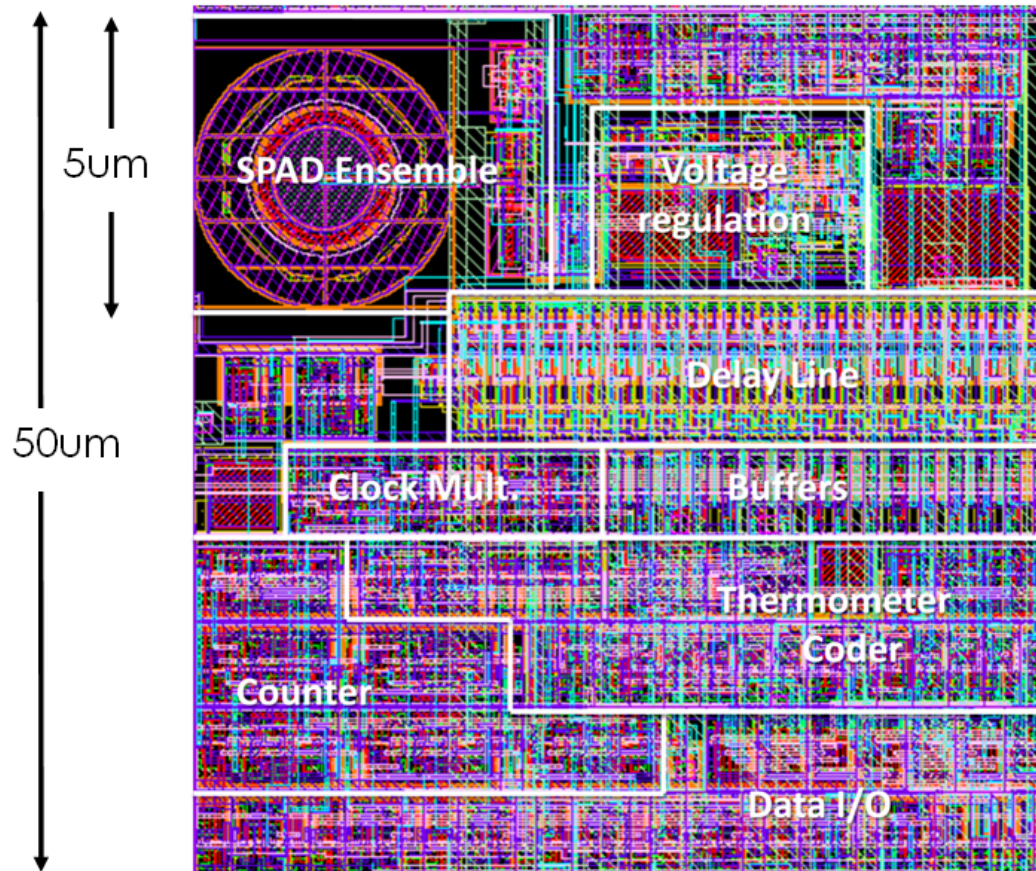


- High fill factor - PDE
- The only way to eliminate the SPAD to TDC propagation delay variation in the Single Photon Timing Resolution
- Heterogeneous technologies
- Electronic flexibility

# Flexibility in digital SPAD design

16/20

- single pixel aspect ratio



Over 500  
transistors  
in  $50 \times 50 \mu\text{m}^2$

can be  
reduced  
depending on  
required  
functionalities

Typically 50/50  
sensitive area  
to electronics

erika.garutti@physik.uni-hamburg.de

Terascale Alliance - Detector workshop, 15/03/12

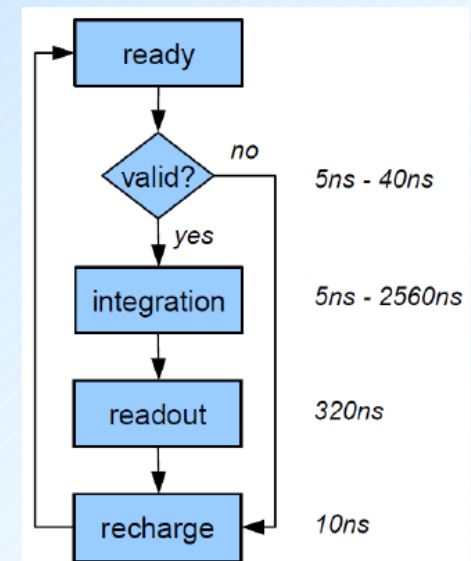
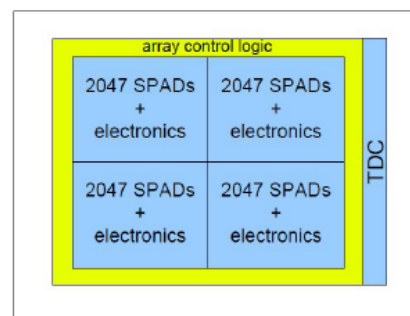
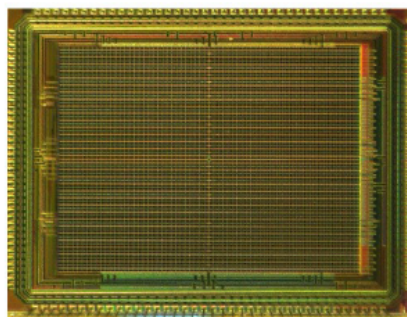
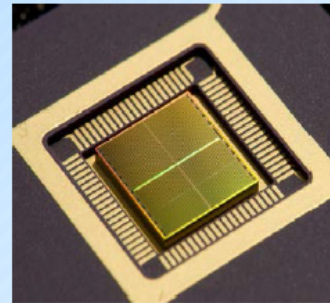
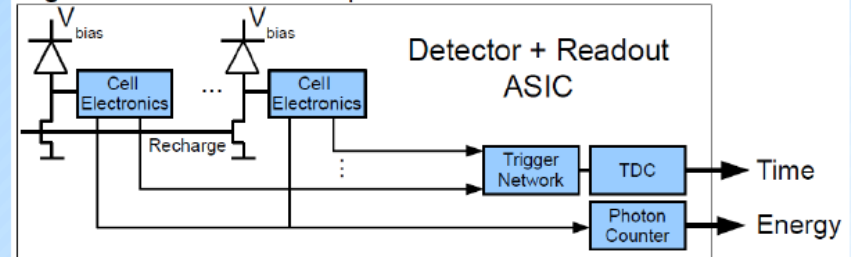
Gersbach, Charbon, et al., Journal of Solid-State Circuits 2012

## dSiPM-Digital SiPM (Philips)

Signal from each pixel is digitized and the information is processed on chip:

- time of first fired pixel is measured
- number of fired pixels is counted
- active control is used to recharge fired cells
- 4 x 2047 micro cells
- 50% fill factor including electronics
- integrated TDC with 8ps resolution

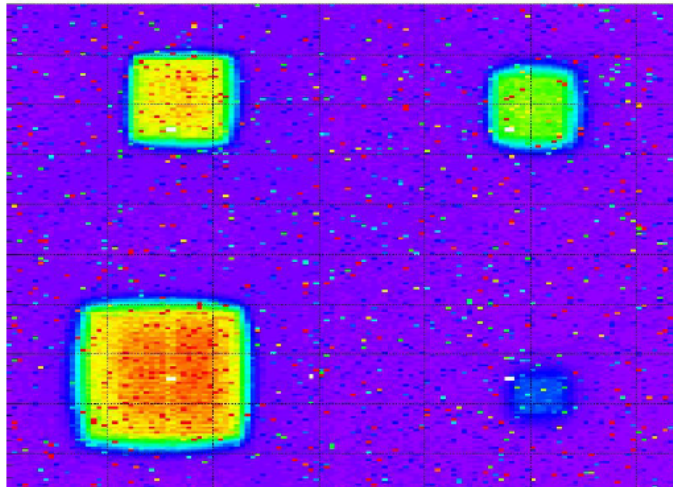
Digital Silicon Photomultiplier Detector



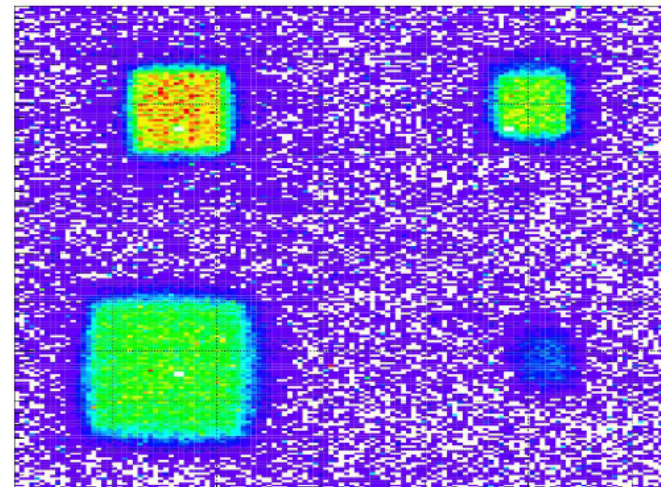
**T. Frach (Philips) @ IEEE2009**



## Digital SiPM – Slow Scan Imaging Mode

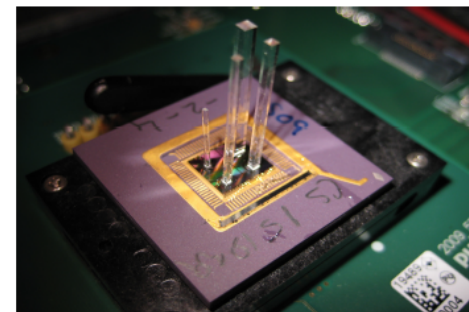


**Singles**



**Coincidences**

- *Spatial sampling of the light distribution*
- *Similar to dark count map measurement*
- *Dark count map can be used for correction*
- *Alternatively, use coincidence to reduce noise*
- *Potentially useful for light guide design*





# SUMMARY

Actual situation now:

- Conventional 1D (analog) Silicon PM
  - PDE(400nm)≈65%
  - PDE>20% for Lxe and Lar (vacuum UV)
  - PDE(905nm)=10÷20%
  - Pixel pitch 5 micron is the smallest one (46190/mm<sup>2</sup>), 15 micron (5000/mm<sup>2</sup>)—is a kind of standard
  - Crosstalk < 10% for 6x6mm<sup>2</sup>, 75 micron pitch (PDE = 50%)
  - < 1% for 1.3x1.3mm<sup>2</sup>, 10 micron pitch (PDE=20%)

◆ Trends for future development:

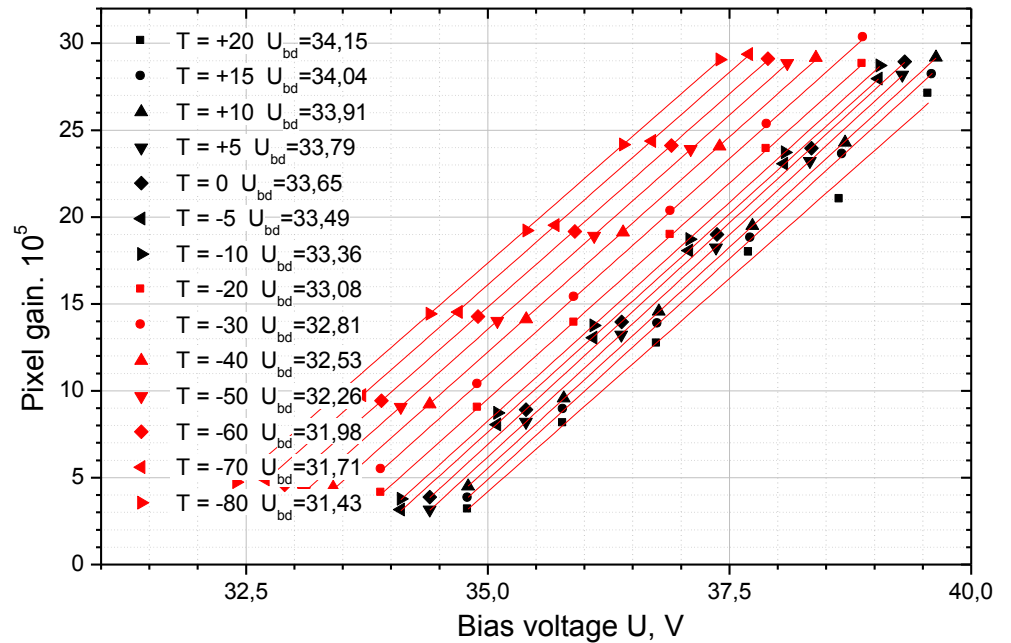
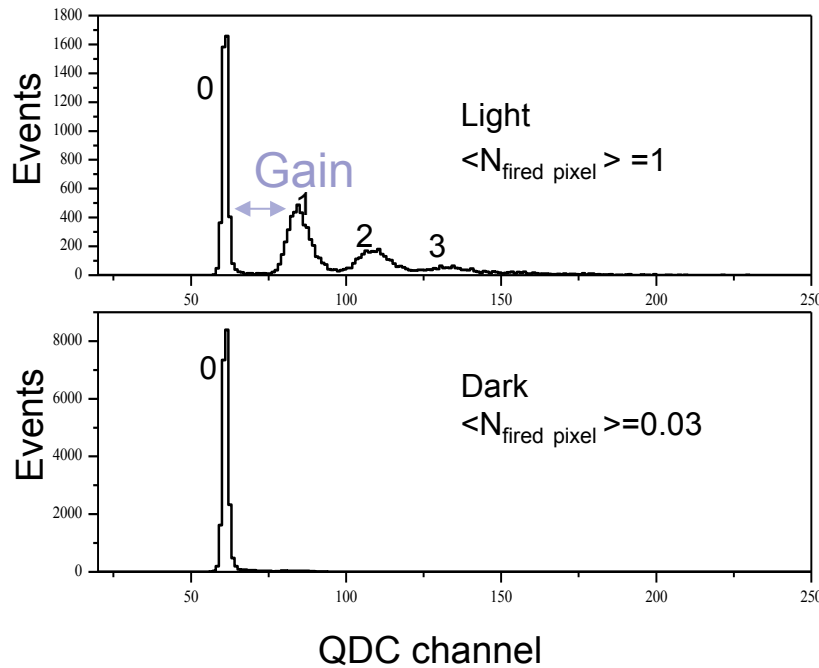
2D (CMOS) and 3D (custom Si or non-Si and CMOS electronics) integration – smart SiPMs with digital information about a number of fired pixels and timestamps

◆ Industrial SiPM production by Broadcom and OnSemi – new era for the SiPM applications





# Main SiPM's parameters. Gain vs voltage for different T



$$G = \frac{C_{\text{pixel}} \cdot (U - U_{\text{breakdown}})}{q}$$

$U_{\text{breakdown}} \rightarrow G=0$  Overvoltage  $\Delta U = U - U_{\text{breakdown}}$

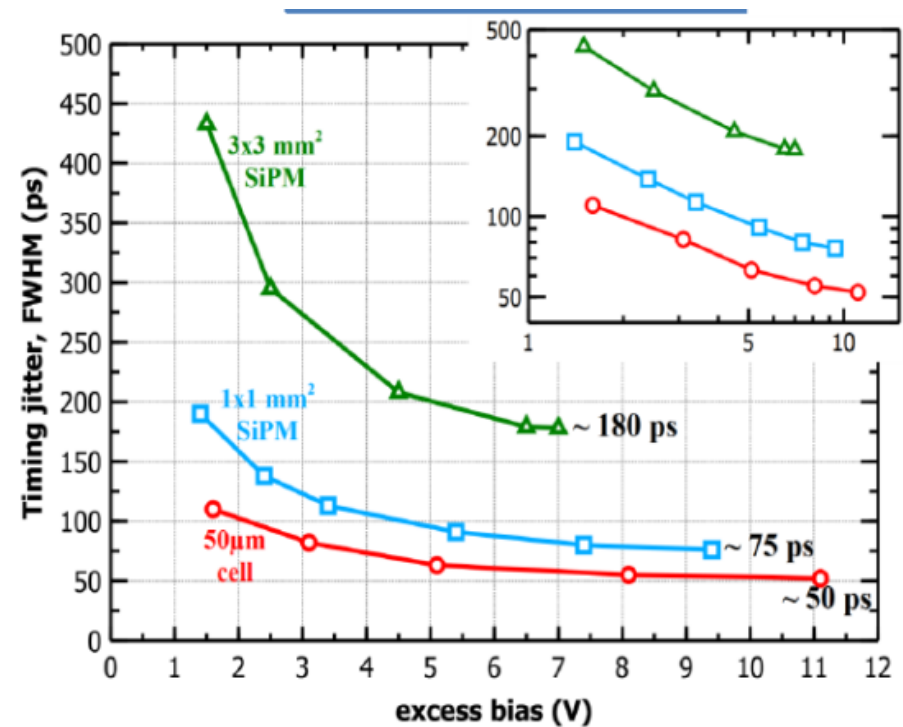
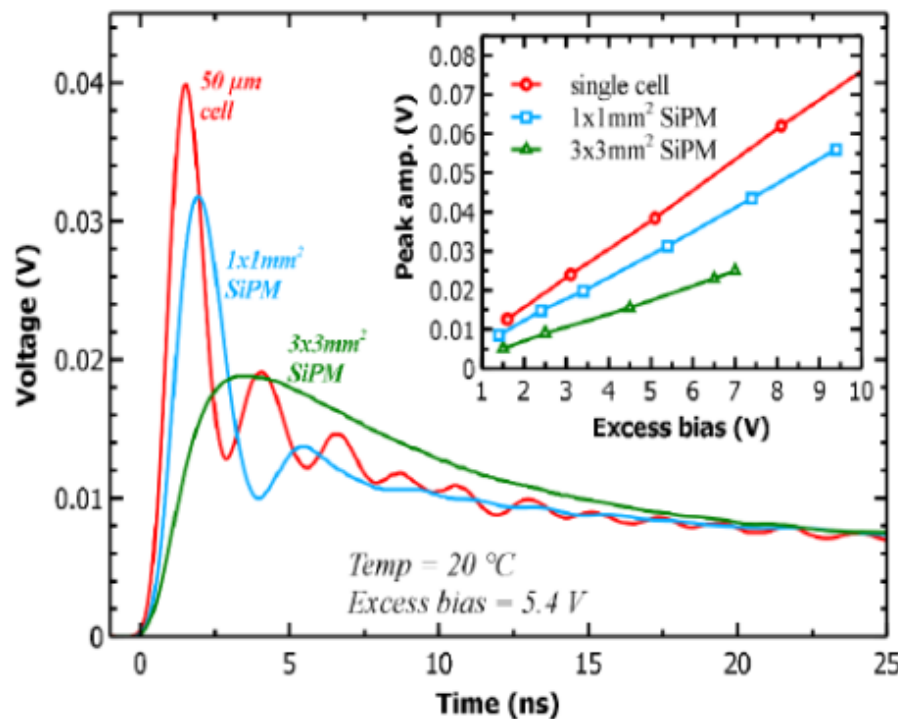
We need to collect SiPM's spectra for different voltages

With temperature decreasing  $U_{\text{breakdown}}$  decreases too – temperature sensitivity

$U_{\text{breakdown}}$  and  $\Delta U$ —are needed for different type SiPM comparison

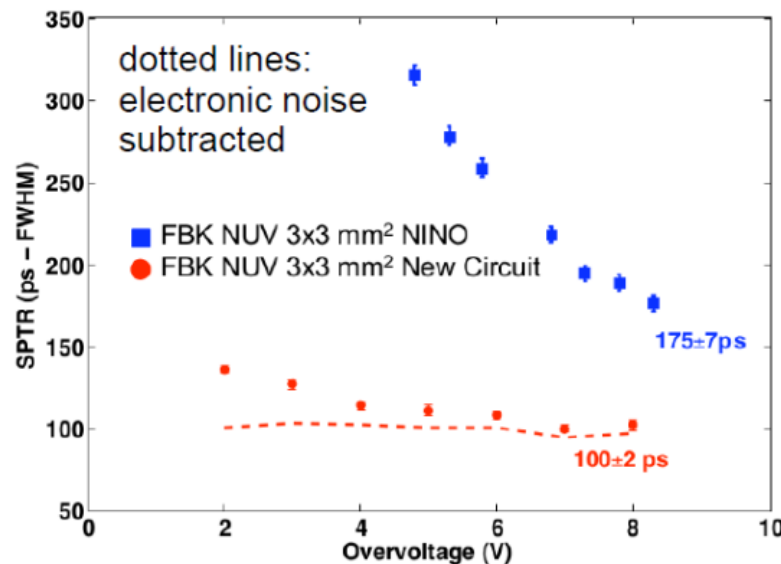
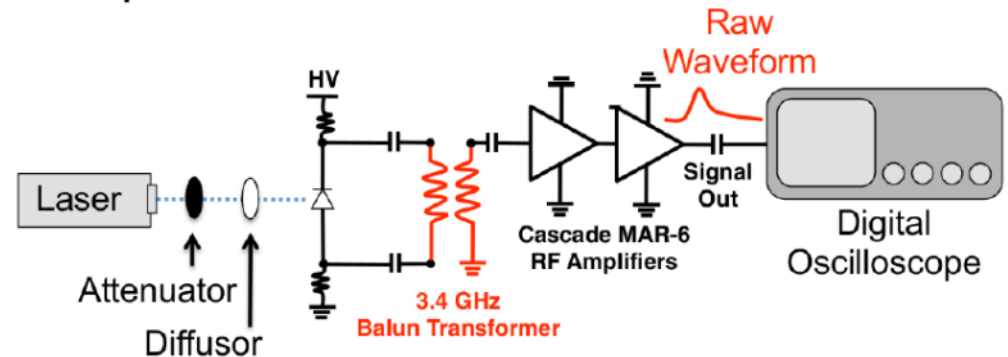
# Main trade-off: fast timing vs large area

- Larger area => higher noise + slower response => lower TR
  - DCR noise  $\sim$  area
  - Electronic noise  $\sim$  capacitance  $\sim$  area
  - Signal rising slope  $\sim$  SER rise time  $\sim$  capacitance



# Compensation of large capacitance by transformer

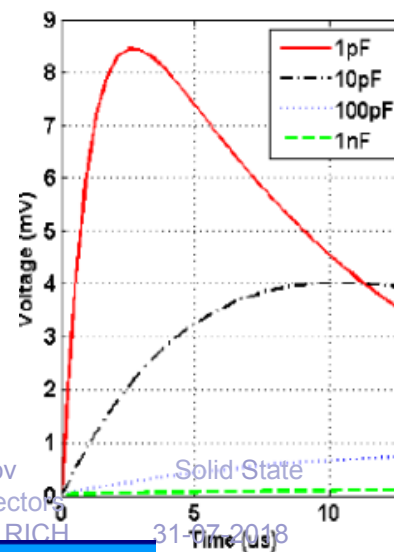
Passive Compensation Circuit:



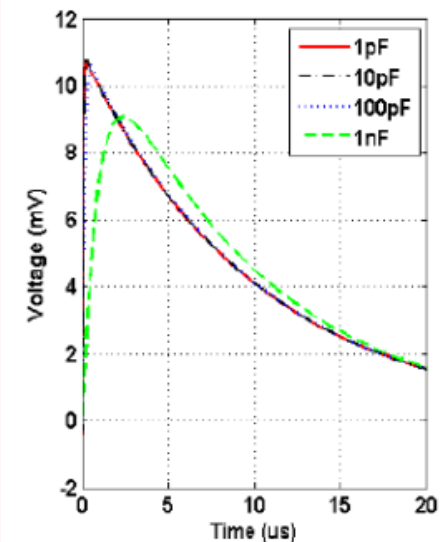
FBK NUV 3x3mm<sup>2</sup> (40μm):

NINO: SPTR=175ps FWHM  
new Circuit: SPTR=100ps FWHM

Detector Pulse Without Compensation



Detector Pulse With Compensation



# SPTR of a stand alone SiPM cell

min threshold, focused 2 micron spot, <200fs

scope LeCroy WaveRunner 620Zi 2GHz

